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Ultra-low voltage embedded processor system for Internet-of-Things microcontrollers

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Title: Ultra-Low Voltage Embedded Processor
System for the Internet of Things Microcontrollers

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Problem description:

It is predicted that billions of embedded devices will soon be connected to the internet. End nodes will typically contain a microcontroller to collect, process, and interpret sensory input data. Many of these will run from small batteries and may need to harvest energy from the environment to achieve an acceptable battery lifetime. The microcontroller typically includes a CPU, memories, buses, and peripherals. The student should design the embedded processor system within the microcontroller.

The system should be able to run from a wide supply voltage range. The system should be implemented in an low- voltage standard cell library using state-of-the-art design techniques.

The system should support voltage scaling from the nominal voltage down to the subthreshold voltage domain, allowing a wide tradeoff between performance and power consumption. The student should analyze the system properties and compare them to an identical system implemented using traditional libraries and design techniques.

Responsible professor: Snorre Aunet, NTNU-IET

Supervisor: Frode Pedersen, ATMEL

Abstract

As devices get an ever increasing foothold on the internet and the Internet of Things becomes the usual landscape in the mass consumer electronic products is necessary to bring embedded processors capable of bringing performance to the micro controllers of such devices. compares Is the intention of this project to compare under different scenarios suitable for the applications two embedded processors form Atmel's one AVR 8-bit and an AVR32 UC3 to identify which is the one that has the lowest power consumption, lowest energy consumption. It has been shown that the AVR has the less power consumption (about half) but in terms of energy the AVR32 is less taxing. A test bench was implemented including SPI communication modules and memories, This is due to the long execution times of the AVR which are for 1.5 to 10 longer than the AVR32. These conclusions scale when implementing on lower feature size (this project uses UMC's 130nm typical process library and UMC's 65 typical process library). Also the conclusion stand when restricting the standard library such that an "Ultra low voltage" friendly net list is produced and tested yielding similar results.

Preface

This Master Thesis was carried out as a part of the study program European Masters in Embedded Computing Systems at Department of Electronics and Telecommunications of the Norwegian University of Science and Technology under the supervision of Prof. Snorre Aunet. The work was done at the Atmel office in Trondheim under the supervision of Frode Pedersen during period between January and July 2014.

Contents

List of Figures	vii
List of Tables	ix
List of Acronyms	xi
1 Introduction	1
1.1 Historical Perspective	2
1.1.1 Internet of Things	2
1.1.2 Related Work	2
1.2 Asigment Interpretation	3
1.3 Contributions	3
1.4 Report Organization	4
2 Background	5
2.1 Power	5
2.1.1 Dynamic Power	5
2.1.2 Static Power	6
2.1.3 Dynamic Voltage Frequency Scaling (DVFS) and Voltage Islands	7
2.1.4 Near- Threshold Voltage (NTC) and Sub-Threshold Voltage (STC)	7
2.2 Heterogenous Computing	8
2.2.1 8/16bit cores vs 32-bit cores	9
3 Implementation	11
3.1 Setup and Work Flow	11
3.1.1 Hardware	12
3.1.2 Software	15
3.2 Synthesis	17
3.2.1 Synthesis script	17
3.2.2 Libraries	18
3.3 Power and Energy Analysis	19
3.3.1 Power	19

3.3.2	Energy	19
4	Results	21
4.1	Synthesis AVR and AVR32	21
4.1.1	Library variation	21
4.1.2	Area Comparison	22
4.1.3	Timing Achieved	22
4.2	Power and Energy comparison between the AVR and AVR32	23
4.2.1	8-bit Math Test	24
4.2.2	8-bit Switch Test	27
4.2.3	16-bit Math Test	30
4.2.4	16-bit Switch Test	33
4.2.5	32-bit Math Test	36
4.2.6	RAM Write Test	39
4.2.7	Serial Peripheral Interface (SPI) Read and Write Test	42
4.2.8	Transfer Control Protocol / Internet Protocol Checksum Computation (TCP/IP Checksum Computation) Test	45
4.2.9	Summary	48
5	Discussion	49
5.1	Synthesis	49
5.1.1	Area	49
5.1.2	Timing	49
5.2	Power and Energy	50
5.2.1	AVR vs AVR32	50
5.2.2	Core vs System	51
5.2.3	NTV and STV	51
5.3	Future Work	51
5.3.1	Test Cases and Peripherals	51
5.3.2	Real STV, NTV and More Libraries	52
5.3.3	Tools and Testing Cores at the Same Time	52
5.3.4	Cores	52
5.4	Conclusions	52
	References	53

List of Figures

2.1	NMOS.[24]	6
2.2	Energy per Operation and Delay vs Voltage.[11]	8
2.3	big.LITTLE system.[13]	9
2.4	8-bit Central Processing Unit (CPU) Comparison[16]	9
2.5	Atmel's Product Range [6]	10
3.1	AVR core (AVR) setup	13
3.2	AVR32 UC core (AVR32) setup	14
4.1	Area footprint	23
4.2	Power Graphs for the 8-bit Math Test	24
4.3	Energy Graphs for the 8-bit Math Test	24
4.4	Power Density Graphs for the 8-bit Math Test	24
4.5	CPU % Power Graphs for the 8-bit Math Test	24
4.6	Power Graphs for the 8-bit Switch Test	27
4.7	Energy Graphs for the 8-bit Switch Test	27
4.8	Power Density Graphs for the 8-bit Switch Test	27
4.9	CPU % Power Graphs for the 8-bit Switch Test	27
4.10	Power Graphs for the 16-bit Math Test	30
4.11	Energy Graphs for the 16-bit Math Test	30
4.12	Power Density Graphs for the 16-bit Math Test	30
4.13	CPU % Power Graphs for the 16-bit Math Test	30
4.14	Power Graphs for the 16-bit Switch Test	33
4.15	Energy Graphs for the 16-bit Switch Test	33
4.16	Power Density Graphs for the 16-bit Switch Test	33
4.17	CPU % Power Graphs for the 16-bit Switch Test	33
4.18	Power Graphs for the 32-bit Math Test	36
4.19	Energy Graphs for the 32-bit Math Test	36
4.20	Power Density Graphs for the 32-bit Math Test	36
4.21	CPU % Power Graphs for the 32-bit Math Test	36
4.22	Power Graphs for the RAM Test	39
4.23	Energy Graphs for the RAM Test	39

4.24 Power Density Graphs for the RAM Test 39
4.25 CPU % Power Graphs for the RAM Test 39
4.26 Power Graphs for the SPI Test 42
4.27 Energy Graphs for the SPI Test 42
4.28 Power Density Graphs for the SPI Test 42
4.29 CPU % Power Graphs for the SPI Test 42
4.30 Power Graphs for the TCP/IP Checksum Test 45
4.31 Energy Graphs for the TCP/IP Checksum Test 45
4.32 Power Density Graphs for the TCP/IP Checksum Test 45
4.33 CPU % Power Graphs for the TCP/IP Checksum Test 45

List of Tables

3.1	Address Map	15
4.1	Area vs targeted time	22
4.2	Timing Achieved for each net-list	23
4.3	Power Comparisons 8-bit Math Test	25
4.4	Energy Comparisons 8-bit Math Test	25
4.5	8-bit Math Energy Estimation for Near-Threshold Voltage (NTV) and Sub-Threshold Voltage (STV)	26
4.6	Power Comparisons 8-bit Switch Test	28
4.7	Energy Comparisons 8-bit Switch Test	28
4.8	8-bit Switch Energy Estimation for NTV and STV	29
4.9	Power Comparisons 16-bit Math Test	31
4.10	Energy Comparisons 16-bit Math Test	31
4.11	16-bit Math Energy Estimation for NTV and STV	32
4.12	Power Comparisons 16-bit Switch Test	34
4.13	Energy Comparisons 16-bit Switch Test	34
4.14	16-bit Switch Energy Estimation for NTV and STV	35
4.15	Power Comparisons 32-bit Math Test	37
4.16	Energy Comparisons 32-bit Math Test	37
4.17	32-bit Math Energy Estimation for NTV and STV	38
4.18	Power Comparisons RAM Test	40
4.19	Energy Comparisons RAM Test	40
4.20	RAM Energy Estimation for NTV and STV	41
4.21	Power Comparisons SPI Test	43
4.22	Energy Comparisons SPI Test	43
4.23	SPI Energy Estimation for NTV and STV	44
4.24	Power Comparisons TCP/IP Checksum Test	46
4.25	Energy Comparisons TCP/IP Checksum Test	46
4.26	TCP/IP Checksum Energy Estimation for NTV and STV	47

List of Acronyms

V_{dd} supply voltage.

V_{th} threshold voltage.

AHB Advance High Performance Bus.

AMBA Advance Microcontroller Bus Architecture.

APB Advance Peripheral Bus.

ARM Advance Risc Machine.

AVR AVR core.

AVR bus AVR Bus System.

AVR32 AVR32 UC core.

CMOS Complementary Metal Oxide Semiconductor.

CPU Central Processing Unit.

DSP Digital Signal Processor.

DVE Discovery Visualization Environment.

DVFS Dynamic Voltage Frequency Scaling.

GPIO General Purpose Input Output.

HDL Hardware Description Language.

I/O Input/ Output.

IoT Internet of Things.

nMOS n-channel Metal Oxide Semiconductor.

NTNU Norwegian University of Science and Technology.

NTV Near-Threshold Voltage.

pMOS p-channel Metal Oxide Semiconductor.

RISC Reduced Instruction Set Computer.

RTL Register Transfer Level.

SAIF file Switching Activity Interchange File.

SoC System on Chip.

SPI Serial Peripheral Interface.

STV Sub-Threshold Voltage.

TCP Transfer Control Protocol.

TCP/IP Checksum Computation Transfer Control Protocol / Internet Protocol
Checksum Computation.

VCD file IEEE standard waveform database dumpfile.

VCS Verilog Compiler Simulator.

VPD file Synopsys waveform database dumpfile.

Chapter 1

Introduction

In today's world the number of devices featuring features enabled by embedded systems is increasing. At the core of these devices there is a System on Chip (SoC) consisting of at least a CPU a General Purpose Input Output (GPIO), a memory and a bus connecting all. From the user /environment perspective the goal of these SoC is to react to stimulus on the GPIO. In a well implemented system the reaction to the stimuli is a appropriate according to a program stored in the memory ran by the CPU. The human machine interfaces for the majority of this systems are very limited or non existent. But these machines are the cornerstone of modern consumer products which features have become standard of living in modern industrialized societies.

At the same time there is a huge pressure towards have higher integration between devices by means of sharing data, collaborating to solve tasks, accessing remote peripherals, producing data, etc. All of that will enable the implementation of interesting and useful features such as load balancing in an electric grid by timing when and where electric consumers can get online and how much power it can be drawn form there. For this to happen SoC besides the CPU, memory GPIO and bus it must contain at least one communication module that enables it to communicate with other devices. And the vast majority of this embedded systems will have limited access to electrical power.

Since the set of tasks that is expected to be performed by the embedded systems varies a lot depending on the application one might be tempted to think that different CPUs will perform better than others performing certain tasks. Parallel to that it is known that the amount of power used by any electronic device is proportional to the squared of the voltage. The juxtaposition of the previous two statements mean that in order to implement an efficient device whose energy consumption is as low as possible -so it can be operated with a constrained power budget like a small battery or by harvesting energy- It is necessary to study different CPUs performing the same tasks. It is also necessary to watch the effect that the use of different

implementations of different on the energy consumption. The goal of this thesis to observe the energy consumption in an 8-bit implementation of Atmel's popular AVR core and in a 32-bit AVR32 and to quantify the impact different process technology and reduced library more suitable to a ultra low voltage library.

1.1 Historical Perspective

1.1.1 Internet of Things

In 1999 Kevin Ashton was the first person to use the term *Internet of Things (IoT)* [2] during a presentation for Procter & Gamble identifying the potential of integrating the RFID technology in the supply chain to gather data and the internet. He points out that most of the information available on the internet has been either been input by a human or triggered by a human action. The accuracy, consistency and flow of this data then is dependent of human accuracy, consistency and latency. Thanks to RFID technology and similar technologies data can be automatically be uploaded to the internet with the accuracy, consistency and latency of machines. Is also Ashton's view that this automatic data gathering capabilities and easy access thru the internet will empower machines to reduce waste, increase efficiency and alert when maintenance task should be performed.

Meanwhile in 2004 an article published on Scientific American [21] made the analogy of the segmentation of different communication protocols for devices to communicate such as ZigBee, Bluetooth, etc. to the Arpanet and other Internet predecessors in the 1960's and makes a very good case why devices should use the same internet standards to exchange information. Among the main advantages identified by the article are packet switched networks, unique addressing for each nodes

1.1.2 Related Work

This work builds on the idea to use the AVR as a coprocessor for the AVR32 exposed in the master thesis of M Sc. Yahsir Mahmood[20]. It is also used a modified version of his test bench for benchmarking the AVR32. On his thesis M. Sc Mahmood goes thru the process of designing an energy efficient AVR Bus System (AVR bus) to Advance Peripheral Bus (APB) needed to access the peripherals with the AVR and the AVR32[20]. In this work however instead of using the AVR bus to APB bridge an AVR bus to Advance High Performance Bus (AHB) bridge is used as it enables the AVR to access the same high performance RAM as the AVR32 and puts the AVR on the same heretical level as AVR32.

1.2 Assignment Interpretation

The following tasks were proposed and executed to address the problem:

Task 1: Set up a test bench that connects RAM, SPI communication modules and other peripherals via an AMBA AHB lite bus with a CPU.

Task 2: Test access to memory and peripherals connected in task 1 using an AVR and an AVR32 and confirm it function correctly.

Task 3: Choose a set of test programs to benchmark that perform tasks of a simple but representative IoT application.

Task 4: Synthesize the set-ups used for task 2 in different feature sizes and with different constraints.

Task 5: Perform power analysis on the results of task 4 running the test programs established on task 3.

Task 6: Compute the energy used to perform each test program under each net-lists.

Upon completion of these tasks data the following objectives are achieved:

Objective 1: Identify the effect on power and energy consumption that constraining the standard cells that the synthesis tool can use under different scenarios.

Objective 2: Identify which scenarios favor the architecture of the AVR32 and which favor the aAVR.

Objective 3: Test if the conclusions from objective 2 stands if feature size is changed.

Objective 4: Extrapolate the energy and power figures if implemented on an ultra low voltage library.

1.3 Contributions

A test bench that accepts any core that interfaces thru AHB bus. Eight different test relevant to the IoT scenario to better understand the power, energy consumption of the AVR and AVR32. A comparison consisting of 640 experiments where libraries and timing contains and feature size core and application were varied to monitor the power and energy consumption and an estimate of what to expect when moving to the STV and NTV domains.

1.4 Report Organization

This report is organized as:

Chapter 1: Introduction Introduces the master thesis, provides some historical perspective, states how the problem was interpreted, how it was approached, summarizes the contributions of the thesis and shows how the report is organized.

Chapter 2: Background Provides the theoretical background on the components of power on a Complementary Metal Oxide Semiconductor (CMOS) circuit, examines some techniques to save power while paying performance penalty such as Dynamic Voltage Frequency Scaling (DVFS) and voltage islands and explains the potentials saving that can be achieved by reducing the voltage near and below the threshold region. Also comments on the advantage of heterogeneous computing and shows two commercial examples.

Chapter 3: Implementation Describe the work flow that was followed, the components that were used, how were used, the tests that were performed and how they were performed the tools that were used for testing.

Chapter 4: Results Shows the result obtained by the methodology proposed. Address each test and extracts and directs attention to interesting facts derived from the results .

Chapter 5: Discussion Analyzes the results and provides some explanations .

Chapter 2

Background

2.1 Power

There are two sources of power dissipation by a CMOS circuit [22]

$$P_{total} = P_{dynamic} + P_{static} \quad (2.1)$$

2.1.1 Dynamic Power

Dynamic power is consumed when changing the logic level the inputs of a gate, this causes the n-channel Metal Oxide Semiconductor (nMOS) and p-channel Metal Oxide Semiconductor (pMOS) transistors to switch. From figure it is appreciated that any switching activity will cause that the pMOS and the nMOS transistors are in the *conducting* state at the same time causing a *short circuit current* to flow between supply voltage (V_{dd}) and *GND*. At the same time the effective load capacitance is discharged or charged causing further power consumption. [22]

$$P_{dynamic} = P_{switching} + P_{short\ circuit} \quad (2.2)$$

It is possible to express:

$$P_{short\ circuit} = I_{short\ circuit} V_{DD} \quad (2.3)$$

Where $P_{short\ circuit}$ is the average short-circuit power, $I_{short\ circuit}$ is the average short-circuit current.

For quantifying the power dissipated by the switching activity we need to know two quantities the effective capacitance driven by the gate and how often this capacity (switching frequency) is charge/discharge. The effective capacitance is dependent of the gate, interconnect and the load. The switching frequency is dependent of the logic and clock frequency. After some mathematics and analysis of the circuit is possible to express the average switching power as: [22]

$$P_{switching} = \alpha C V_{DD}^2 f \quad (2.4)$$

Where $P_{switching}$ is the average switching power, α is the *activity factor* that expresses in terms of the clock frequency the charging/ discharging, C is the *effective capacitance* and f is the clock frequency.

2.1.2 Static Power

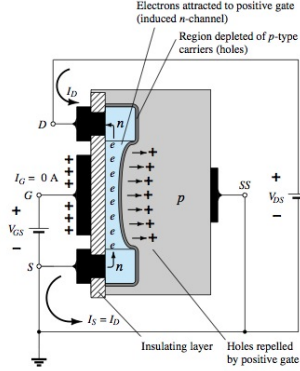


Figure 2.1: NMOS.[24]

Static power for CMOS has three main contributors. Subthreshold leakage, gate leakage drain and source diffusion leakage.[22]

$$P_{static} = (I_{sub} + I_{gate} + I_{junct})V_{DD} \quad (2.5)$$

Figure 2.1 shows the junction of semiconductor materials that form an pMOS transistor. Thru these junctions and thanks to minority carriers there is a leakage current. The gate leakage can be reduced by substituting the silicon dioxide with high dielectric materials between the gate and the semiconductor substrate.[12] Leakage of the junctions can be reduced by doping [1]and voltage on the body[8].

When operating on the subthreshold region the MOS transistor then can be modeled as bipolar transistor as shown by Figure bla the and equation 2.6 describes the behavior of the current flowing from drain to source.[22]

$$I_{sub} = I_{ds0} e^{\frac{V_{gs} - V_{t0} + \eta V_{ds} - \kappa \gamma V_{sb}}{n v_T}} \left(1 - e^{-\frac{V_{ds}}{v_T}} \right) \quad (2.6)$$

Where I_{ds0} is the current at threshold it is dependent of process and geometry, V_{gs} is the voltage between the gate and source, V_{t0} threshold voltage when $V_{source} = V_{body}$, η DIBL coefficient, V_{ds} voltage between drain and source, $\kappa \gamma$ body effect (geometry, dielectric, surface potential, etc), V_{sb} Voltage between source and body, v_T Termal voltage. [22]

From equations 2.5 and 2.3 have a linear dependency to V_{DD} , but is worth noticing that I_{sub} is exponentially dependant of V_{ds} at the same time equation 2.4 shows a quadratic dependency to V_{DD} . Then it is shown that lowering the operating voltage is a way to save power. Nevertheless reducing the voltage can degrade the performance as it reduces de current that goes from drain to source and with that the time that is required to drive the loads increasing delays.

2.1.3 Dynamic Voltage Frequency Scaling (DVFS) and Voltage Islands

DVFS scaling is a technique used to save power. It reduces de voltage and frequency when the work load is low (meaning the timing constrains are more relaxed) and increases the voltage and frequency when the work load is high (meaning the timing contains are tighter). For achieving an energy efficient implementation it is required that voltage/ frequency regulator is an efficient one, the granularity of the voltage and frequency to choose from allow to adapt at any processor workload. The main goal is to consume less energy, this means that the power savings for a task must be greater than the time increase for the same task.[7]

It is possible to have different voltages on a SoC this technique is known as voltage islands. Each island operates on a different voltage level .This technique allows blocks to be grouped together on an island where the voltage presents the right compromise between the power savings and performance degradation. It does not require the regulation overhead that DVFS and it is not aware of the workload situation. [14]

2.1.4 Near- Threshold Voltage (NTC) and Sub-Threshold Voltage (STC)

As stated in the previously, reducing the voltage dramatically reduce the power consumed. Figure 2.2 shows the relationship between the energy spent for operation, the delay and the supply voltage. More energy is saved from the transition from super-thresholdvoltage to NTV than form NTV to STV this is due to the increase in leakage that is observed when $V_{dd} < \text{threshold voltage } (V_{th})$. The same figure also shows an exponential growth on the delay in the STV region. It is of particular interest the existence of a minimum on the energy per operation curve that indicates there is a voltage in the sub-threshold region that is optimum form the energy perspective but comes at the cost of increased delay. [11]

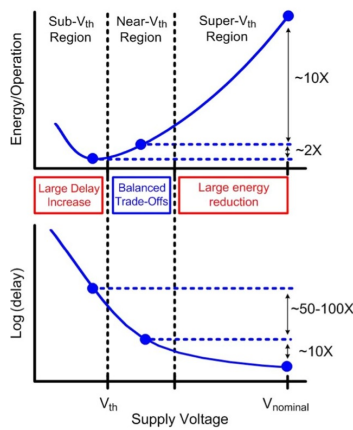


Figure 2.2: Energy per Operation and Delay vs Voltage.[11]

2.2 Heterogenous Computing

Kummar et al. have shown that higher energy efficiency can be achieved on a SoC by using heterogenous cores.[17] By definition an heterogenous core system is a multi-core system made up by different cores. There are difference in terms of energy efficiency, performance, power consumption and capabilities between different cores. There are energy efficient cores that are suitable for simple operations and high performance cores capable of performing complex task but the power consumption is high. Having both on the same SoC allow to have the best of both worlds.

Industry have taken notice of this and there are examples of heterogenous multi-cores that feature an energy efficient core and a high performance core being deployed such as:

Advance Risc Machine (ARM) exploits the energy efficiency of the Cortex- A7 core (*LITTLE*) and the high performance of the Cortex- A15 (*big*) in its *big.LITTLE* architecture shown on Figure 2.3. ARM is quick to notice that despite labeling the Cortex-A7 as *LITTLE* it features micro-architecture advances that culminates on performance than implementations of the Cortex-A8 at a fraction of the power.[13]

NVIDIA uses a power optimized Cortex A9 core(companion core) and four performance optimized Cortex A9 cores (main cores) in its *Tegra 3* formerly known as *Kal-El*. The companion core is limited to 500MHz [23]

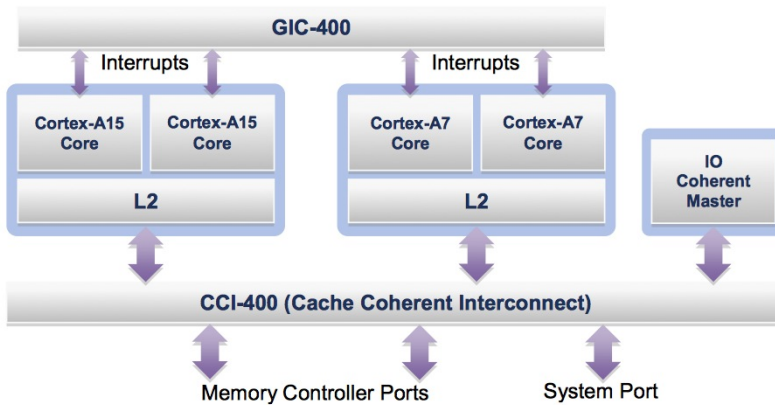


Figure 2.3: big.LITTLE system.[13]

2.2.1 8/16bit cores vs 32-bit cores

Since the smbedded systems environment is diverse, system performance is difficult to define. Some applications require realtime guarantees, others require high precision and/or fast measurement peripherals, others have very limited energy/power contains and finally there are the ones that require lots of computing power.[16] Figure 2.4a shows the benchmark obtained after running the code on Figure 4.2b. It is shown that the AVR is a good candidate to be considered for be a *LITTLE* like co- processor. For an heterogenous system. 8/16 bit processors have the problem that they not support

CPU Architectures	Code size (bytes)	Execution time (cycles)
8051	112	9384
PIC16	87	2492
AVR	46	335

(a) Code Size and Execution

```
int max(int *array)
{
    char a;
    int maximum=-32768;

    for (a=0;a<16;a++)
        if (array[a]>maximum)
            maximum=array[a];
    return (maximum);
}
```

(b) Sample Code

Figure 2.4: 8-bit CPU Comparison[16]

large memory space since the majority of them feature only 16.bit address bus. This an other limitations have open the door for 32-bit cores that might be not the right solution due its increase complexity, Nevertheless there are application areas that require some of the extra performance offered by the 32-bit alternative for a small part

10 2. BACKGROUND

of the application providing further motivation for an heterogenous architecture.[16]
Figure 2.5 Shows Atmel's portfolio for 8-bit and 32-bit micro controllers.

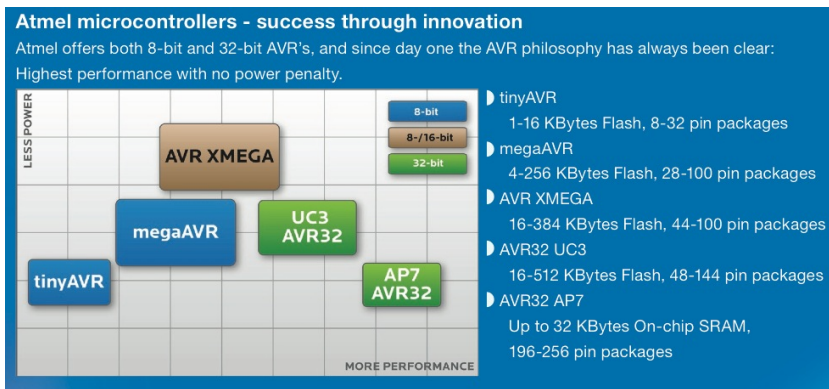


Figure 2.5: Atmel's Product Range [6]

Chapter 3 Implementation

This chapter is divided in three sections. Setup and Work Flow covers the hardware and test cases used for this project. Synthesis explains how the synthesis was performed and declares the libraries used to produce the net-lists on which the power analysis was performed. And the power analysis section go thru the generation of the reports and data gathering and manipulation. Data that is presented in Chapter 4

3.1 Setup and Work Flow

This section is divided into two main parts. The first part describes the hardware used and the second describes the software used. It is very important to note that there is no silicon used for this project.

The basic work flow is as follows:

- Step 1:** The hardware is defined at the RTL level and a test program is prepared.
- Step 2:** Synopsys' Verilog Compiler Simulator (VCS) to produce a Synopsys waveform database dumpfile (VPD file).
- Step 3:** Verify the correct functionality using Discovery Visualization Environment (DVE).
- Step 4:** Test case is prepared on C or asm and compile them with AVR-toolchain or AVR32-toolchain (depending on the targeted processor) to produce the executable.
- Step 5:** Use executable, VCS, and DVE to check function, start and end times of the program or interesting subroutine.
- Step 6:** Use Synopsys' design compiler and synthesis script to produce the appropriate net-list and save it for future usage.

Step 7: Transform the VPD file into a IEEE standard waveform database dumpfile (VCD file) and this into a Switching Activity Interchange File (SAIF file) for this last transformation the tool requires the start and end time of interest.

Step 8: Use Synopsys' design compiler and power analysis script with the net-list generated on step 6 and the SAIF file on the step 7

Step 9: Extract and analyze the data outputted on the power report generated on step 8.

3.1.1 Hardware

In order to be able to compare the energy consumption of the AVR32 and the AVR they must be tested under the same circumstances. Figure 3.2 and 3.1 show the test environments for both processors. As it is shown the test environments are as similar as it can be. The only mayor difference is that the AVR setup includes a bridge AVR bus to AHB. This bridge is not necessary for the AVR32 since it has native interface for AHB.

3.1.1.1 AVR32 UC core

The AVR32 is a Super Harvard architecture 32-bit processor that features a compact Reduced Instruction Set Computer (RISC) instruction set including Digital Signal Processor (DSP) instructions fully orthogonal. This processor has two AHB interfaces one for the program memory and other for data and peripheral communication, RAM interface, 15 32-bit wide general purpose registers 32-bit wide stack pointer, program counter and link register. It is a 3- stage pipeline processor allowing one instruction per clock cycle for most instructions.[5]

3.1.1.2 AVR core

The AVR is a Harvard architecture 8-bit RISC processor. It has 32 registers 8-bits wide, The last six is are concatenated in pairs to form a 16-bit wide pointers to address the data space. Since it is a Harvard architecture the program memory and the data memory are not only physically separated but they have separate address spaces, separate data and address lines and the data memory is accessed by using the same instructions as the Input/ Output (I/O). [4]

The AVR data bus is synchronous based on master/ slave scene and has 16-bit for addresses, 8-bit for data from the master, 8-bits for data from the slave, write, read, wait, single bus cycle and burst signals. This bus allow single access operation, this means that on the same clock cycle the master puts the address on the address lines and either send data or receives it and is ready for another operation on the next clock cycle if there is no wait signal form the slave.[3]

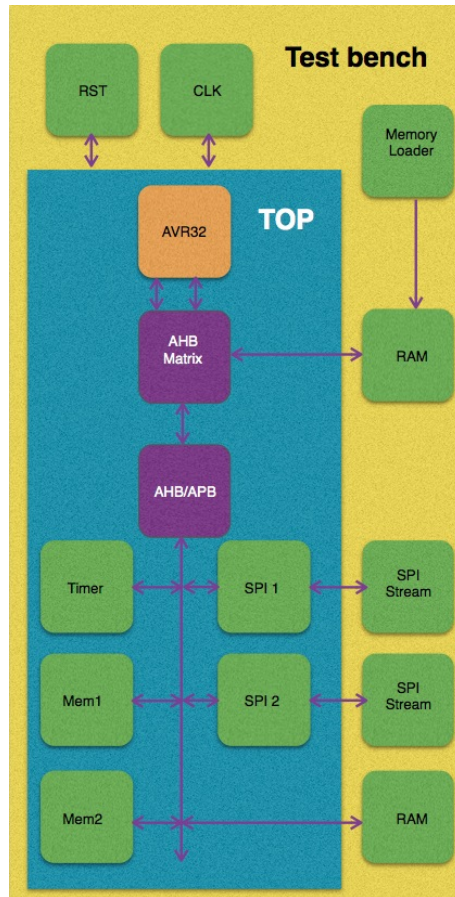


Figure 3.2: AVR32 setup

write¹ and simple read that allow the slaves to add wait states.

3.1.1.4 Top and Test bench

Figure 3.2 and Figure 3.1 shows what is instantiated at the top level and how it interfaces with the test bench. The top-level include the processor core (**AVR** or **AVR32**) **AHB**, **APB** busses -in the case of the **AVR** the **AHB to AVR bus**- two **SPI** modules a timer, two memory modules. The test bench has the clock generator, **RAMs**, program memory and the program memory loader that takes the **.hex** file and loads the memory with it.

¹Due the mismatch between the 32-bit wide data bus from the **AHB** and the 8-bit wide data bus from the **AVR** bus all write operations are a read/ modify operations

Peripheral	Base Address
AHB RAM	0x00000000
APB RAM	0xFFFF0000
Timer	0xFFFF2000
SPI 1	0xFFFF3000
SPI 2	0xFFFF4000
Mem 1	0xFFFF0000
Mem 2	0xFFFF0000

Table 3.1: Address Map

Table 3.1 shows the peripherals with it is corresponding Base Address.

3.1.2 Software

This section explains what the each test do. All this were written in C (except for the case of the SPI for the AVR which was written in assembly) and compiled by the AVR toolchain and AVR32 toolchain to produce the executable code needed by the processors.

All the test were proposed thinking on an IoT scenario were a micro controller gets data from a sensor via a communication peripheral (SPI was chosen due its simplicity and huge popularity), the communication is bidirectional -the data streams are simulated by the test bench- performs some arithmetic manipulation (addition correcting systematic error and multiplication for sensitivity error correction), testing this value against a parameter and use Transfer Control Protocol (TCP) to connect to the internet. Due to board range of applications for the arithmetic manipulation three tests were proposed -8, 16, and 32 bit- and due to the unknown amount of cases to be handled two tests were proposed -8 and 16 bit-. The TCP is a complex protocol and with the support given by media access hardware undefined it is difficult to specify what to test. The computing the check sum of a TCP packet was chosen due to its importance when determining data integrity and assuming simple hardware that implements complete functionality for layers 1 to 3 of the OSI model.

3.1.2.1 8-bit Math Test

This test in its main defines two 8-bit operands and calls a function that adds and a function that multiplies. It takes 4340ns for the AVR and 1220ns for the AVR32 to finish.

3.1.2.2 8-bit Switch Test

This test in its main defines a 8-bit operand and calls a function that selects the case and returns a 8-bit value to the main. It takes 1700ns for the AVR and 980ns for the AVR32 to finish.

3.1.2.3 16-bit Math Test

This test in its main defines two 16-bit operands and calls a function that adds and a function that multiplies. It takes 5680ns for the AVR and 1340ns for the AVR32 to finish.

3.1.2.4 16-bit Switch Test

This test in its main defines a 16-bit operand and calls a function that selects the case and returns a 16-bit value to the main. It takes 2120ns for the AVR and 980ns for the AVR32 to finish.

3.1.2.5 32-bit Math Test

This test in its main defines two 32-bit operands and calls a function that adds and a function that multiplies. It takes 10720ns for the AVR and 1160ns for the AVR32 to finish.

3.1.2.6 RAM Write Test

This test in its main performs 100 RAM writes. It takes 30340ns for the AVR and 6640ns for the AVR32 to finish.

3.1.2.7 SPI Read and Write Test

This test its main sets up SPI 1, SPI 2, then performs 10 times a SPI read on SPI 1, a multiplication, 8-bit shift and a write on SPI 2. The program for the AVR first configures the bridge to access the I/O space and then proceeds to do the same as the program for the AVR32 and after that it configures back the bridge to address the memory space. It takes 18820ns for the AVR and 8560ns for the AVR32 to finish.

3.1.2.8 TCP/IP Checksum Computation Test

This test in its main computes the check sum field of a 120 byte TCP frame. which is a set of 16-bit sum, shift and byte swap operations. It takes 37220ns for the AVR and 7900ns for the AVR32 to finish.

3.2 Synthesis

The goal of the synthesis is to translate the Register Transfer Level (RTL) code to a net-list of interconnected logic gates chosen from a library.

The synthesis is done by the Synopsys' design compiler following the instructions and contains stated by the synthesis scripts.

Performing the synthesis is paramount for this project. Changes done on the constrains and library selection produced the variation in results that will be presented on Chapter 4 and discussed on Chapter 5. To produce a net-list a library is chosen, a clock period is targeted and a maximum area is defined. For all cases the maximum area set to zero knowing it will be impossible to the tool to achieve this but will force the tool to get the smallest possible, the tool is also instructed to do its best effort. Per each library used ten clock periods were targeted, from 1ns to 10ns with a step of one nano second. Additionally the tool is intructed to keep the hierarchy -this is don e so the power analysis is heriarchial as well-

3.2.1 Synthesis script

The script commands the tool to do:

Step 1: Analyze.

Step 2: Elaborate.

Step 3: Link.

Step 4: Load the library with the standard cells.

Step 5: Load the constrains (area, timing, wire model).

Step 6: Compile the design (clock gating is performed at this stage).

Step 7: Write net-lists.

The set of steps defined before will produce a net list that would be used on power and energy analysis described later this chapter. Ideally for this project a STV or NTV library should be used for this project but no such library was available so a super threshold voltage library was restricted to simulate the restriction in terms of gates that are present in a subthreshold voltage libraries.

The synthesis tool produces the following reports:

Area: Reports the area taken by the combinational logic, non combinational and sequential and the hierarchical distribution.

Clock Gating: Shows the elements that are clock gated with its inputs, outputs and related registers. Presents the elements that were not able to be clock gated and the violation that will occur if gated. It also displays a summary with the number of clock gating elements, the number of registers gated, the number of registers ungated.

Resources: Reports on the resources shared by the modules, the implementations and the multiplexors added.

Power: Presents a power consumption estimate.

Timing: Shows critical paths, different points on the path and the time it takes from point to point. Gives a summary on the required data time and the arrival of that data and computes the slack.

References: Reports the cells that were used, library of origin, area per cell number of cells used and the total area that type of cell takes on the design

All Violators: Reports on the modules that violate the timing and the area constraints and by how much it is missed.

3.2.2 Libraries

Two base libraries were used to produce the net-list used in this thesis. UMC's 130nm FSC0H_D generic core and UMC's 65nm FSE0K_D generic core. To see the effect of feature size on energy consumption. For the understanding the effects of a 130nm low voltage library two the cells available for the synthesis tool in two different stages. Both of this libraries are super-threshold voltage. There was no sub-threshold voltage nor near-threshold voltage available.

3.2.2.1 UMC's FSC0H_D Generic Core

No restrictions

This is a high performance 130nm library that provide support arithmetic cells for data-path design. The corner used was typical process 1.2 V at 25°C with a gate density of 250000 gates per mm² featuring a drawn gate length of 0.12μm with a power consumption of 6nW/MHz/gate[9].

Restricted (ltd)

For these synthesis the tool was not allowed to use any gate with more inputs than two and the maximum outputs is two as well. This is the most restricted the library can get.

Restricted (ltd2)

For these synthesis the tool was allowed to use the same gates as the (ltd) case plus gates with a fan-in and fan-out of three.

3.2.2.2 UMC's FSE0K_D Generic Core

This is a low leakage 65nm library that provide support arithmetic cells for data-path design. The corner used was typical process 1.2 V at 25°C with a gate density of 900000 gates per mm² featuring a drawn gate length of 0.06μm with a power consumption of 1.9nW/MHz/gate[10].

3.3 Power and Energy Analysis

3.3.1 Power

Before doing the power analysis two things have to be ready. A net list produced by the synthesis tool and a SAIF file that contains the switching activity caused by a test program. For the power analysis again Synopsys' design compiler is used with a report power script. The power script first it loads the library data base, it is very important to use the same library used during the synthesis. Then it reads the SAIF file and reports the power used by each component of the top level and the total power.

3.3.2 Energy

The energy is obtained by multiplying the power (average power) results obtained by the report of the power analysis and multiply it by the time spent on the task (the time difference between the end time and start time used for generating the SAIF file) both the energy and power results are only valid for the test case being studied on the net list tested, since at its core it was generated with the switching activity the program caused. For purpose of this thesis the effects described on Section 2.1.4 will be estimated a black box and the results described shown by Figure 2.2 apply directly system wide. By using the (3.1) the total energy consumption is estimated where Δ energy consumption factor expressed as the ratio of the energy consumed when changing form the super-threshold voltage to the NTV or STV this wil yield to E_{total} being the energy consumed by the system under the NTV or STV conditions.

$$E_{total} = \Delta E_{total\ Super} \quad (3.1)$$

Based on Johnsen preliminary results[15] for the design of the *Full-Custom SubNear-Threshold Cell Library in 130nm CMOS* the values used for the STV case (350mV) $\Delta = 0.072$ and for the NTV case (400mV) $\Delta = 0.094$. Only the result produced by netlist with a target clock period of 10ns will be used for the estimation. The net-list 130nmltd will be used for NTV and STV and the 130ltd2 ones for NTV.

Chapter 4

Results

In this section the results of the synthesis process with the different restrictions and the power analysis data will be presented in graph.

4.1 Synthesis AVR and AVR32

Ten different clock periods were targeted to produce ten net lists for each core set-up (AVR or AVR32) and library (UMC's FSC0H_D Generic Core -130nm-, UMC's FSC0H_D Generic Core Restricted -130nm-, UMC's FSC0H_D Generic Core Restricted -130nm- or UMC's FSE0K_D Generic Core) a total of 80 net lists-65nm-.

4.1.1 Library variation

4.1.1.1 UMC's FSC0H_D Generic Core Unrestricted (130nm)

This is the base case. Against the results obtained by this set of net lists comparisons will be made since all the available cells are used and power optimization technique clock gating was done successfully.

4.1.1.2 UMC's FSC0H_D Generic Core Restricted (130nm)

This case is the best substitute candidate for a subthreshold voltage since all the gates with fan-ins and fan-outs larger than two were restricted. The clock gating cells were restricted so no clock gating was not performed. This case also takes the largest surface on the wafer.

4.1.1.3 UMC's FSC0H_D Generic Core Restricted (130nm)

This case is the best substitute candidate for a STV since all the gates with fan-ins and fan-outs larger than three were restricted. The clock gating cells were restricted

so no clock gating was not performed. This case also takes the largest surface on the wafer.

4.1.1.4 UMC's FSE0K_D Generic Core (65nm)

This case give us information on how power, area and timing scales for the super-threshold operation it is important as a reference point to observe the effect that feature size has on power and energy. This case also takes the smallest surface on the wafer.

4.1.2 Area Comparison

Figure 4.1 shows that for every case and every core restricting the clock period below certain point causes the area to increase -around 4 ns for the AVR32 and around 3 ns AVR. Table 4.1 show some interesting comparisons that help us to watch the effects of the library constriction and core selection.

Target ($ns/\mu m^2$)	130nm		130nm1td		130nm1td2		65nm	
	AVR	AVR32	AVR	AVR32	AVR	AVR32	AVR	AVR32
1	160634.	347241.	316990.	714925.	301690.	675180.	41094.4	99675.8
2	147715.	343153.	313741.	716474.	295957.	677208.	38298.6	92870.7
3	143369.	336020.	296455.	697892.	283271.	655172.	33063.	73243.8
4	130395.	284294.	285102.	636489.	273185.	609820.	30820.8	65494.4
5	125878.	269527.	280718.	625014.	270459.	598123.	30456.6	63887.7
6	124987.	266066.	280163.	619191.	269422.	596939.	30056	62560.3
7	124535.	264314.	279270.	614902.	269146.	587792.	29964.8	61721.6
8	124333.	260168.	279156.	608965.	268594.	587566.	29899.8	61392.3
9	124255.	256329.	279073.	607360.	268558.	582834	29817.9	61009.3
10	124250.	255328	279068.	607254.	268501.	581165.	29815.4	60802.2

Table 4.1: Area vs targeted time

4.1.3 Timing Achieved

Table 4.2 shows that for every case and every core restricting the clock period below certain point causes the synthesis tool to fail to achieve the timing goal -around 4 ns for the AVR32 and around 3 ns AVR and there is minimum clock period achieved -around 3.1 ns for the AVR32 and 2 ns for the AVR using 130nm feature size-. For the 65nm library the minimum clock period is smaller -around 1.7 ns AVR and 2.4 ns for the AVR32-.

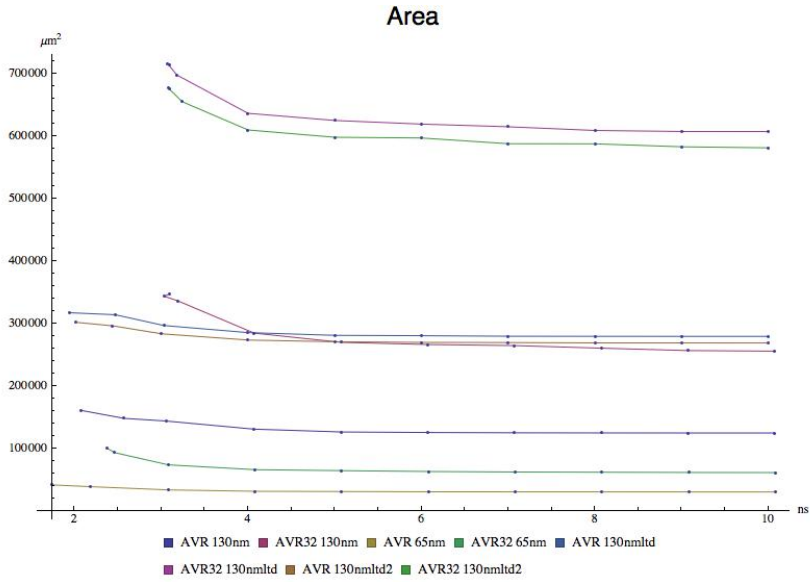


Figure 4.1: Area footprint

Target (ns)	130nm		130nm1td		130nm1td2		65nm	
	AVR	AVR32	AVR	AVR32	AVR	AVR32	AVR	AVR32
1	2.07	3.09	1.94	3.1	2.01	3.09	1.74	2.38
2	2.57	3.04	2.47	3.07	2.44	3.08	2.18	2.46
3	3.06	3.19	3.03	3.18	3	3.24	3.08	3.08
4	4.07	4.07	4	4	4	4	4.08	4.08
5	5.07	5.07	5	5	5	5	5.08	5.08
6	6.07	6.07	6	6	6	6	6.08	6.08
7	7.07	7.07	7	7	7	7	7.08	7.08
8	8.07	8.07	8	8	8	8	8.08	8.08
9	9.07	9.07	9	9	9	9	9.08	9.08
10	10.07	10.07	10	10	10	10	10.08	10.08

Table 4.2: Timing Achieved for each net-list

4.2 Power and Energy comparison between the AVR and AVR32

4.2.1 8-bit Math Test

4.2.1.1 Super Threshold Voltage

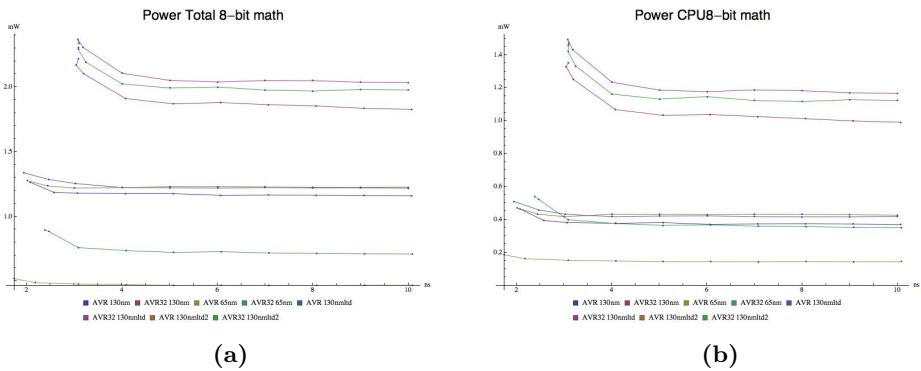


Figure 4.2: Power Graphs for the 8-bit Math Test

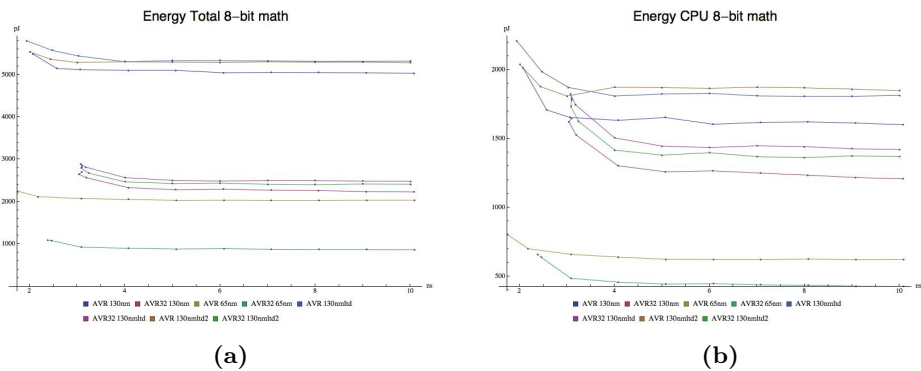


Figure 4.3: Energy Graphs for the 8-bit Math Test

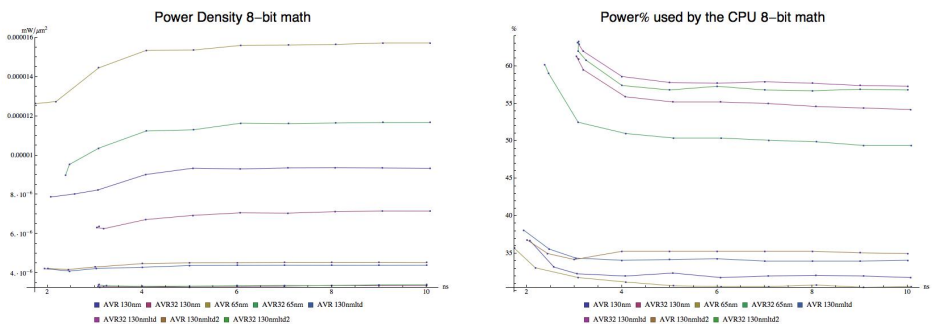


Figure 4.4: Power Density Graphs for the 8-bit Math Test

Figure 4.5: CPU % Power Graphs for the 8-bit Math Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 130nm	1.83	1.58	1.65	3.38	2.68	2.87
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 130nmltd	1.84	1.66	1.71	3.32	2.79	2.93
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 130nmltd2	1.85	1.61	1.69	3.28	2.59	2.8
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 65nm	1.81	1.51	1.59	3.23	2.44	2.63
$\left(\frac{\text{AVR32ltd}}{\text{AVR32}}\right)$ 130nm	1.11	1.05	1.1	1.18	1.09	1.15
$\left(\frac{\text{AVR32ltd2}}{\text{AVR32}}\right)$ 130nm	1.08	1.04	1.06	1.13	1.07	1.1
$\left(\frac{\text{AVR3265}}{\text{AVR32130}}\right)$ nm	0.41	0.36	0.39	0.4	0.32	0.36
$\left(\frac{\text{AVRltd}}{\text{AVR}}\right)$ 130nm	1.08	1.04	1.06	1.16	1.1	1.12
$\left(\frac{\text{AVRltd2}}{\text{AVR}}\right)$ 130nm	1.05	1.01	1.04	1.16	1.01	1.13
$\left(\frac{\text{AVR65}}{\text{AVR130}}\right)$ nm	0.41	0.4	0.4	0.41	0.38	0.39

Table 4.3: Power Comparisons 8-bit Math Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 130nm	0.51	0.44	0.46	0.95	0.75	0.81
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 130nmltd	0.52	0.47	0.48	0.93	0.78	0.82
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 130nmltd2	0.52	0.45	0.47	0.92	0.73	0.79
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)$ 65nm	0.51	0.43	0.45	0.91	0.69	0.74
$\left(\frac{\text{AVR32ltd}}{\text{AVR32}}\right)$ 130nm	1.11	1.05	1.1	1.18	1.09	1.15
$\left(\frac{\text{AVR32ltd2}}{\text{AVR32}}\right)$ 130nm	1.08	1.04	1.06	1.13	1.07	1.1
$\left(\frac{\text{AVR3265}}{\text{AVR32130}}\right)$ nm	0.41	0.36	0.39	0.4	0.32	0.36
$\left(\frac{\text{AVRltd}}{\text{AVR}}\right)$ 130nm	1.08	1.04	1.06	1.16	1.1	1.12
$\left(\frac{\text{AVRltd2}}{\text{AVR}}\right)$ 130nm	1.05	1.01	1.04	1.16	1.01	1.13
$\left(\frac{\text{AVR65}}{\text{AVR132}}\right)$ nm	0.41	0.4	0.4	0.41	0.38	0.39

Table 4.4: Energy Comparisons 8-bit Math Test

In Figure 4.2a it is observed that the power consumption for the systems using the AVR is very similar for the 130nm1td2 and 130nm1td cases when targeting clock periods larger than 4ns, when targeting periods smaller there is a transition around 3ns and in the vicinity of 2ns the 1301td2 behaves similar to the 130nm case mainly because the power consumption of the later grows faster than the 130nm1td. Figure 4.2b shows that the AVR 130nm1td2 core consumes more power than its counterparts the but the effect described earlier it is present here as well and around the 3ns it is surpassed by the 130nm1td. The power consumption of the AVR32 65nm is comparable with the power consumption with the implementations of the AVR cores using the 130nm library. Figure 4.3a shows that systems with AVR32 cores consume half the energy than the ones based on the AVR core, however Figure 4.3b shows that if we compare just cores AVR32 cores energy expenditure is only 80% (on average) the energy used by the AVR cores. Figure 4.5Timing restriction around 3ns produces AVR core that the smallest power fraction under the 130nm1td2 case.

4.2.1.2 NTV and STV

(pJ)	65nm	130nm	130 1td2	130 1td
AVR				
Super TV	2035.46	5034.4	5281.78	5320.84
NTV	—	—	496.487	500.159
STV	—	—	—	383.1
AVR32				
Super TV	866.2	2228.94	2411.94	2481.48
NTV	—	—	226.722	233.259
STV	—	—	—	178.667

Table 4.5: 8-bit Math Energy Estimation for NTV and STV

4.2.2 8-bit Switch Test

4.2.2.1 Super Threshold Voltage

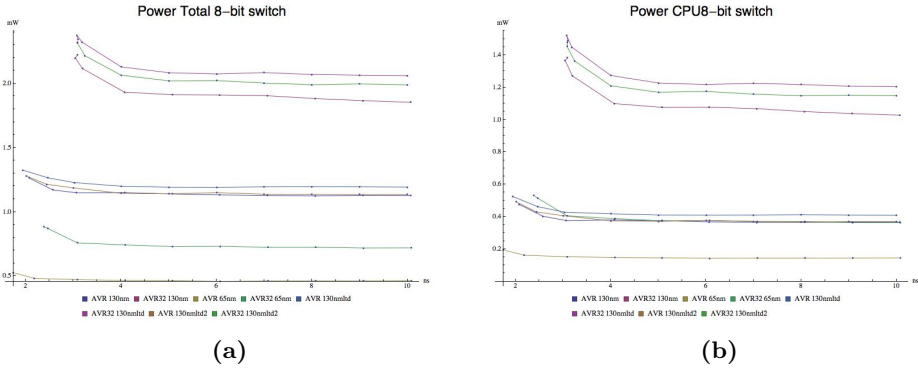


Figure 4.6: Power Graphs for the 8-bit Switch Test

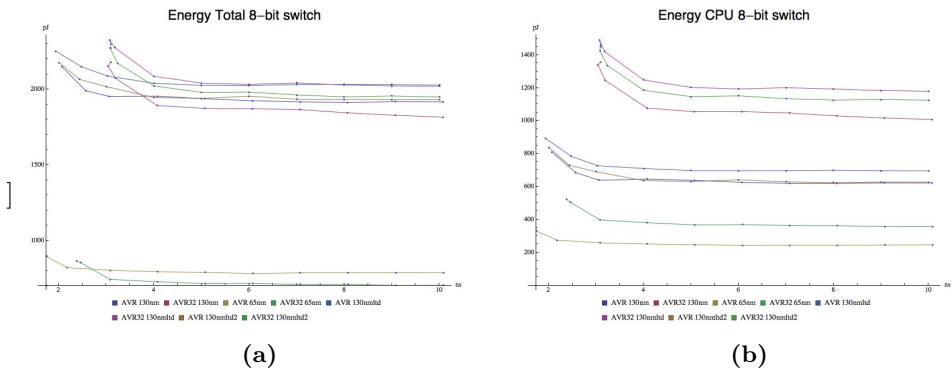


Figure 4.7: Energy Graphs for the 8-bit Switch Test

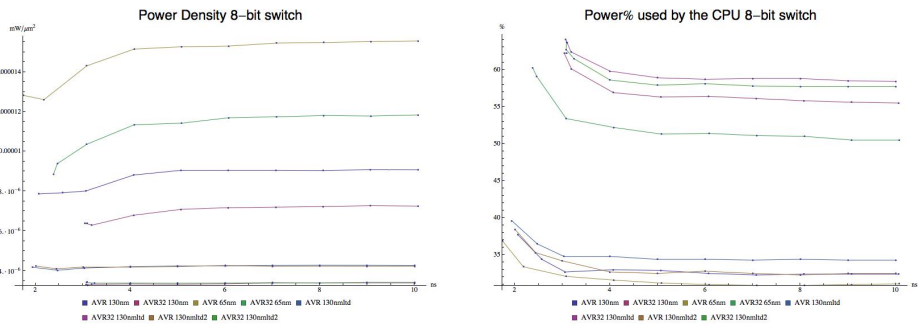


Figure 4.8: Power Density Graphs for the 8-bit Switch Test

Figure 4.9: CPU % Power Graphs for the 8-bit Switch Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$(\frac{AVR32}{AVR})130nm$	1.88	1.64	1.72	3.39	2.81	2.98
$(\frac{AVR32}{AVR})130nm\text{ ltd}$	1.89	1.73	1.77	3.39	2.84	3.04
$(\frac{AVR32}{AVR})130nm\text{ ltd2}$	1.91	1.75	1.79	3.39	3.01	3.17
$(\frac{AVR32}{AVR})65nm$	1.81	1.55	1.61	3.19	2.52	2.67
$(\frac{AVR32\text{ ltd}}{AVR32})130nm$	1.11	1.05	1.09	1.17	1.08	1.14
$(\frac{AVR32\text{ ltd2}}{AVR32})130nm$	1.07	1.04	1.06	1.12	1.06	1.09
$(\frac{AVR3265}{AVR32130})nm$	0.4	0.36	0.38	0.38	0.32	0.35
$(\frac{AVR\text{ ltd}}{AVR})130nm$	1.08	1.04	1.06	1.15	1.09	1.12
$(\frac{AVR\text{ ltd2}}{AVR})130nm$	1.04	1.	1.01	1.08	0.99	1.02
$(\frac{AVR65}{AVR130})nm$	0.42	0.41	0.41	0.41	0.39	0.39

Table 4.6: Power Comparisons 8-bit Switch Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$(\frac{AVR32}{AVR})130nm$	1.08	0.95	0.99	1.96	1.62	1.72
$(\frac{AVR32}{AVR})130nm\text{ ltd}$	1.09	1.	1.02	1.95	1.64	1.75
$(\frac{AVR32}{AVR})130nm\text{ ltd2}$	1.1	1.01	1.03	1.95	1.73	1.83
$(\frac{AVR32}{AVR})65nm$	1.04	0.89	0.93	1.84	1.45	1.54
$(\frac{AVR32\text{ ltd}}{AVR32})130nm$	1.11	1.05	1.09	1.17	1.08	1.14
$(\frac{AVR32\text{ ltd2}}{AVR32})130nm$	1.07	1.04	1.06	1.12	1.06	1.09
$(\frac{AVR3265}{AVR32130})nm$	0.4	0.36	0.38	0.38	0.32	0.35
$(\frac{AVR\text{ ltd}}{AVR})130nm$	1.08	1.04	1.06	1.15	1.09	1.12
$(\frac{AVR\text{ ltd2}}{AVR})130nm$	1.04	1.	1.01	1.08	0.99	1.02
$(\frac{AVR65}{AVR132})nm$	0.42	0.41	0.41	0.41	0.39	0.39

Table 4.7: Energy Comparisons 8-bit Switch Test

Figure 4.6a it is observed that the power consumption for the systems using the AVR for the 130nmltd2 and 130nm cases. Figure 4.6b shows that the all the AVR based on the 130nm library consumes more or less the power than the AVR32 65nm. Figure 4.7a shows that all systems based on the 130nm library the differences on energy consumption are small or null around the 4ns target, the same effect is observed around the 3ns mark for the systems using the 65nm library. Figure 4.3b shows the same behavior described for the power consumed by the cpus expenditure is only 80% (on average) the energy used by the AVR cores. Figure 4.9 shows two groups the ones based on the AVR32 architecture and the ones based on the AVR architecture. It is interesting to note that for the AVR 130nm core fraction being near 3ns smaller than the one near the 4ns and the AVR32 65nm is significant less.

4.2.2.2 NTV and STV

(pJ)	65nm	130nm	130 ltd2	130 ltd
AVR				
Super TV	788.8	1917.6	1931.2	2028.1
NTV	—	—	181.533	190.641
STV	—	—	—	146.023
AVR32				
Super TV	705.6	1815.94	1949.22	2019.78
NTV	—	—	183.227	189.859
STV	—	—	—	145.424

Table 4.8: 8-bit Switch Energy Estimation for NTV and STV

4.2.3 16-bit Math Test

4.2.3.1 Super Threshold Voltage

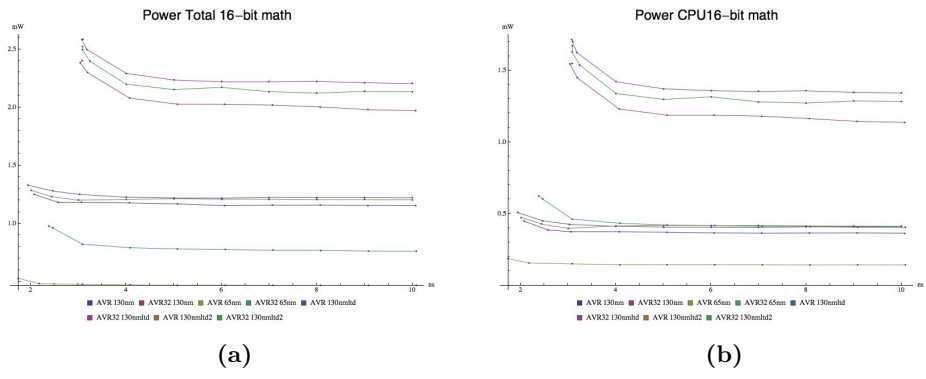


Figure 4.10: Power Graphs for the 16-bit Math Test

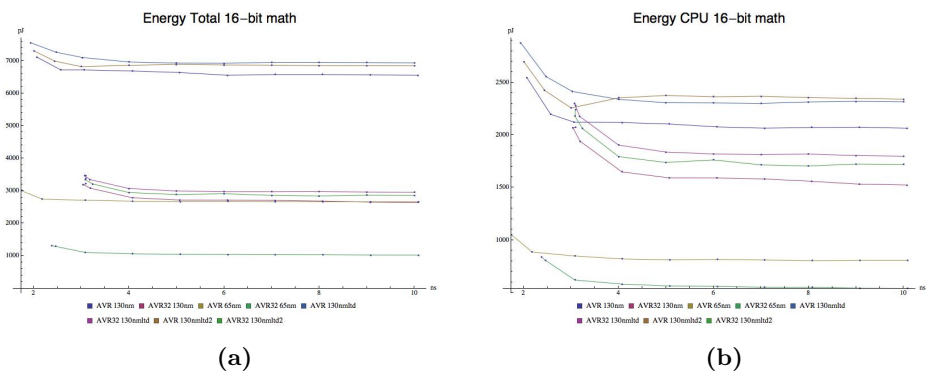


Figure 4.11: Energy Graphs for the 16-bit Math Test

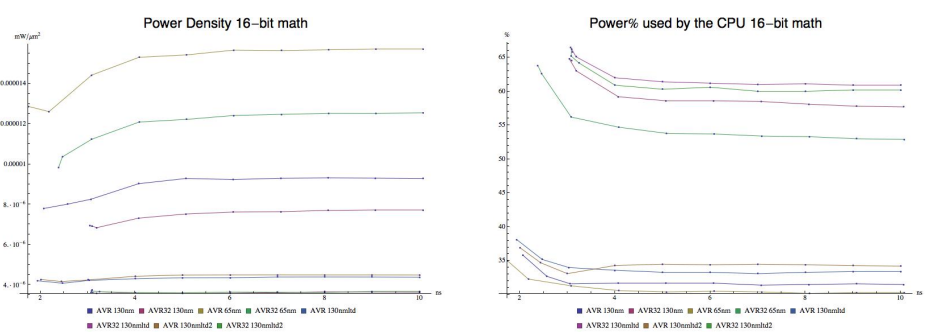


Figure 4.12: Power Density Graphs for Figure 4.13: CPU % Power Graphs for the 16-bit Math Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)130\text{nm}$	2.01	1.71	1.8	3.99	3.13	3.38
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)130\text{nm}1\text{td}$	2.02	1.81	1.87	3.82	3.29	3.44
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)130\text{nm}1\text{td}2$	2.03	1.76	1.84	3.87	3.07	3.31
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)65\text{nm}$	1.99	1.63	1.71	3.86	2.84	3.06
$\left(\frac{\text{AVR32}1\text{td}}{\text{AVR32}}\right)130\text{nm}$	1.12	1.08	1.1	1.18	1.1	1.15
$\left(\frac{\text{AVR32}1\text{td}2}{\text{AVR32}}\right)130\text{nm}$	1.08	1.04	1.06	1.13	1.05	1.09
$\left(\frac{\text{AVR32}65}{\text{AVR32}130}\right)\text{nm}$	0.41	0.36	0.39	0.4	0.32	0.36
$\left(\frac{\text{AVR}1\text{td}}{\text{AVR}}\right)130\text{nm}$	1.08	1.04	1.06	1.16	1.1	1.12
$\left(\frac{\text{AVR}1\text{td}2}{\text{AVR}}\right)130\text{nm}$	1.05	1.02	1.04	1.15	1.06	1.12
$\left(\frac{\text{AVR65}}{\text{AVR130}}\right)\text{nm}$	0.42	0.4	0.41	0.41	0.39	0.39

Table 4.9: Power Comparisons 16-bit Math Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)130\text{nm}$	0.48	0.4	0.43	0.94	0.74	0.8
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)130\text{nm}1\text{td}$	0.48	0.43	0.44	0.9	0.78	0.81
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)130\text{nm}1\text{td}2$	0.48	0.41	0.44	0.91	0.72	0.78
$\left(\frac{\text{AVR32}}{\text{AVR}}\right)65\text{nm}$	0.47	0.38	0.4	0.91	0.67	0.72
$\left(\frac{\text{AVR32}1\text{td}}{\text{AVR32}}\right)130\text{nm}$	1.12	1.08	1.1	1.18	1.1	1.15
$\left(\frac{\text{AVR32}1\text{td}2}{\text{AVR32}}\right)130\text{nm}$	1.08	1.04	1.06	1.13	1.05	1.09
$\left(\frac{\text{AVR32}65}{\text{AVR32}130}\right)\text{nm}$	0.41	0.36	0.39	0.4	0.32	0.36
$\left(\frac{\text{AVR}1\text{td}}{\text{AVR}}\right)130\text{nm}$	1.08	1.04	1.06	1.16	1.1	1.12
$\left(\frac{\text{AVR}1\text{td}2}{\text{AVR}}\right)130\text{nm}$	1.05	1.02	1.04	1.15	1.06	1.12
$\left(\frac{\text{AVR65}}{\text{AVR132}}\right)\text{nm}$	0.42	0.4	0.41	0.41	0.39	0.39

Table 4.10: Energy Comparisons 16-bit Math Test

In Figure 4.10a shows a group for the AVR cores and another for the AVR32 under the 130nm library. The same effect is noted on Figure 4.10b with the AVR3265nm on the same group as the AVR cores based on 130nm library Figure 4.11a exhibits the same grouping behavior described for the power case with the note that the AVR 65nm system is clustered with the systems with AVR32 130nm. Figure 4.3b displays that if we compare just cores AVR32 cores energy expenditure is only 80% (on average) the energy used by the AVR cores. Figure 4.5 Timing restriction around 3ns produces AVR core that the smallest power fraction under the 130nmltd2 case.

4.2.3.2 NTV and STV

(pJ)	65nm	130nm	130 ltd2	130 ltd
AVR				
Super TV	2663.92	6554.72	6844.4	6935.28
NTV	—	—	643.374	651.916
STV	—	—	—	499.34
AVR32				
Super TV	1022.42	2641.14	2856.88	2953.36
NTV	—	—	268.547	277.616
STV	—	—	—	212.642

Table 4.11: 16-bit Math Energy Estimation for NTV and STV

4.2.4 16-bit Switch Test

4.2.4.1 Super Threshold Voltage

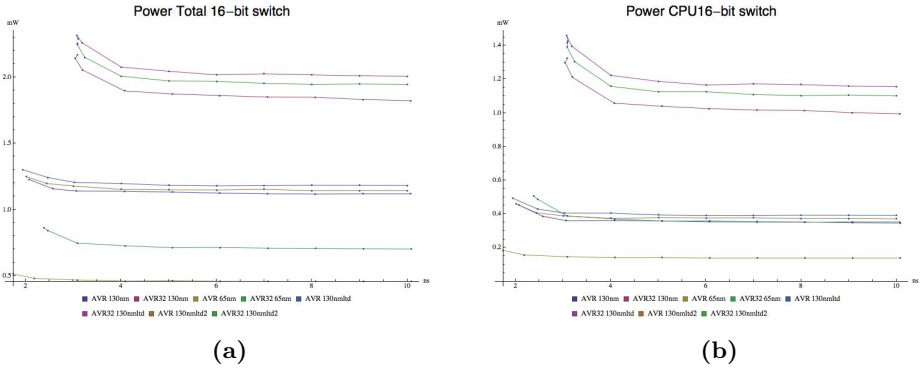


Figure 4.14: Power Graphs for the 16-bit Switch Test

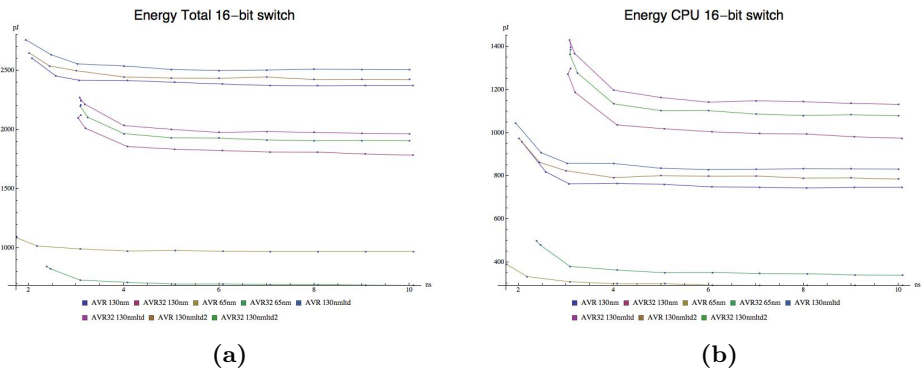


Figure 4.15: Energy Graphs for the 16-bit Switch Test

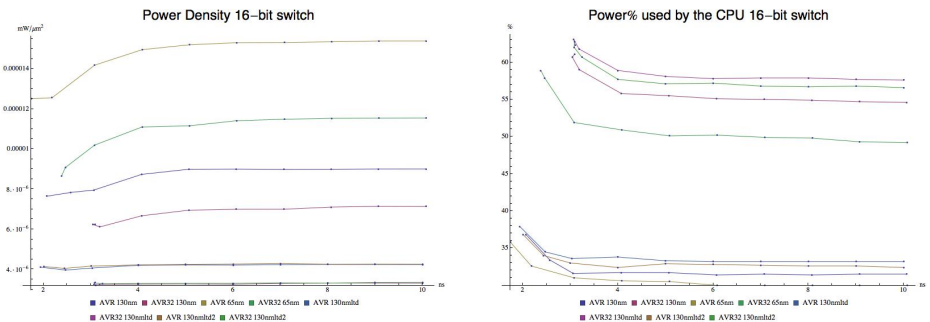


Figure 4.16: Power Density Graphs for Figure 4.17: CPU % Power Graphs for the 16-bit Switch Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nm	1.85	1.63	1.7	3.36	2.82	2.98
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd	1.88	1.7	1.75	3.45	2.89	3.06
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd2	1.88	1.69	1.75	3.42	2.94	3.08
$(\frac{\text{AVR32}}{\text{AVR}})$ 65nm	1.75	1.53	1.58	3.11	2.51	2.64
$(\frac{\text{AVR32ltd}}{\text{AVR32}})$ 130nm	1.1	1.06	1.09	1.16	1.08	1.14
$(\frac{\text{AVR32ltd2}}{\text{AVR32}})$ 130nm	1.07	1.04	1.05	1.11	1.07	1.09
$(\frac{\text{AVR3265}}{\text{AVR32130}})$ nm	0.4	0.36	0.38	0.38	0.32	0.35
$(\frac{\text{AVRltd}}{\text{AVR}})$ 130nm	1.07	1.05	1.06	1.12	1.09	1.11
$(\frac{\text{AVRltd2}}{\text{AVR}})$ 130nm	1.03	1.01	1.02	1.08	1.02	1.05
$(\frac{\text{AVR65}}{\text{AVR130}})$ nm	0.42	0.4	0.41	0.41	0.39	0.4

Table 4.12: Power Comparisons 16-bit Switch Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nm	0.86	0.75	0.78	1.56	1.3	1.38
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd	0.87	0.78	0.81	1.59	1.34	1.42
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd2	0.87	0.78	0.81	1.58	1.36	1.42
$(\frac{\text{AVR32}}{\text{AVR}})$ 65nm	0.81	0.71	0.73	1.44	1.16	1.22
$(\frac{\text{AVR32ltd}}{\text{AVR32}})$ 130nm	1.1	1.06	1.09	1.16	1.08	1.14
$(\frac{\text{AVR32ltd2}}{\text{AVR32}})$ 130nm	1.07	1.04	1.05	1.11	1.07	1.09
$(\frac{\text{AVR3265}}{\text{AVR32130}})$ nm	0.4	0.36	0.38	0.38	0.32	0.35
$(\frac{\text{AVRltd}}{\text{AVR}})$ 130nm	1.07	1.05	1.06	1.12	1.09	1.11
$(\frac{\text{AVRltd2}}{\text{AVR}})$ 130nm	1.03	1.01	1.02	1.08	1.02	1.05
$(\frac{\text{AVR65}}{\text{AVR132}})$ nm	0.42	0.4	0.41	0.41	0.39	0.4

Table 4.13: Energy Comparisons 16-bit Switch Test

The case for 16-bit math and 16-bit switch have very similar results. The only thing that strikes out is that the energy consumption for both the system and the CPU is smaller when using an AVR

4.2.4.2 NTV and STV

(pJ)	65nm	130nm	130 ltd2	130 ltd
AVR				
Super TV	973.08	2372.28	2423.16	2505.84
NTV	—	—	227.777	235.549
STV	—	—	—	180.42
AVR32				
Super TV	687.96	1785.56	1906.1	1965.88
NTV	—	—	179.173	184.793
STV	—	—	—	141.543

Table 4.14: 16-bit Switch Energy Estimation for NTV and STV

4.2.5 32-bit Math Test

4.2.5.1 Super Threshold Voltage

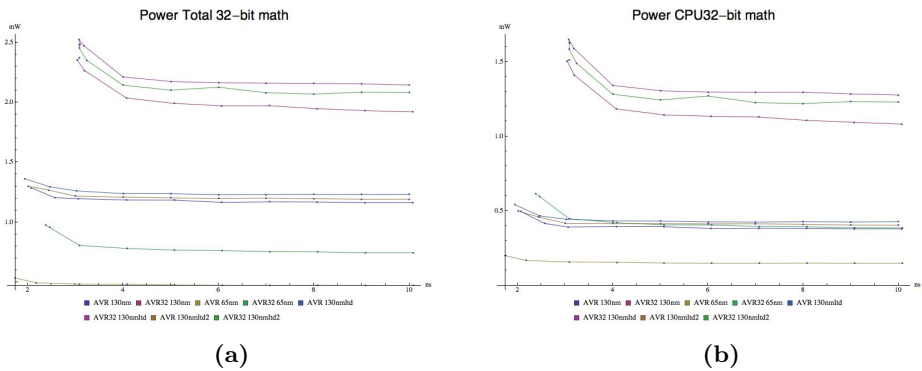


Figure 4.18: Power Graphs for the 32-bit Math Test

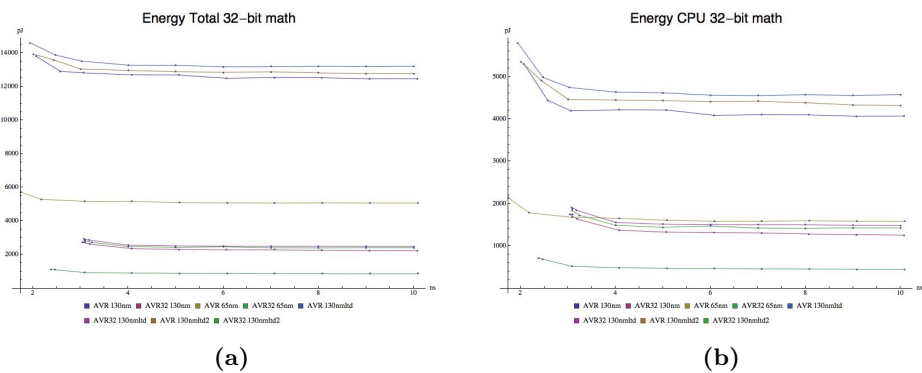


Figure 4.19: Energy Graphs for the 32-bit Math Test

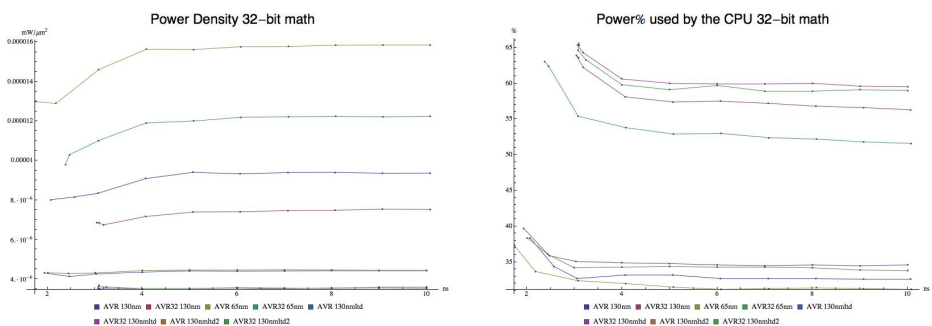


Figure 4.20: Power Density Graphs for Figure 4.21: CPU % Power Graphs for the 32-bit Math Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nm	1.95	1.65	1.75	3.63	2.85	3.08
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd	1.96	1.74	1.8	3.59	2.99	3.14
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd2	1.94	1.73	1.8	3.57	2.97	3.15
$(\frac{\text{AVR32}}{\text{AVR}})$ 65nm	1.94	1.58	1.66	3.58	2.6	2.82
$(\frac{\text{AVR32ltd}}{\text{AVR32}})$ 130nm	1.12	1.05	1.09	1.18	1.08	1.14
$(\frac{\text{AVR32ltd2}}{\text{AVR32}})$ 130nm	1.08	1.04	1.06	1.14	1.05	1.09
$(\frac{\text{AVR3265}}{\text{AVR32130}})$ nm	0.41	0.36	0.39	0.41	0.32	0.36
$(\frac{\text{AVRltd}}{\text{AVR}})$ 130nm	1.07	1.05	1.06	1.13	1.09	1.11
$(\frac{\text{AVRltd2}}{\text{AVR}})$ 130nm	1.05	1.01	1.02	1.1	1.01	1.06
$(\frac{\text{AVR65}}{\text{AVR130}})$ nm	0.41	0.4	0.41	0.4	0.38	0.39

Table 4.15: Power Comparisons 32-bit Math Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nm	0.21	0.18	0.19	0.39	0.31	0.33
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd	0.21	0.19	0.2	0.39	0.32	0.34
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd2	0.21	0.19	0.2	0.39	0.32	0.34
$(\frac{\text{AVR32}}{\text{AVR}})$ 65nm	0.21	0.17	0.18	0.39	0.28	0.31
$(\frac{\text{AVR32ltd}}{\text{AVR32}})$ 130nm	1.12	1.05	1.09	1.18	1.08	1.14
$(\frac{\text{AVR32ltd2}}{\text{AVR32}})$ 130nm	1.08	1.04	1.06	1.14	1.05	1.09
$(\frac{\text{AVR3265}}{\text{AVR32130}})$ nm	0.41	0.36	0.39	0.41	0.32	0.36
$(\frac{\text{AVRltd}}{\text{AVR}})$ 130nm	1.07	1.05	1.06	1.13	1.09	1.11
$(\frac{\text{AVRltd2}}{\text{AVR}})$ 130nm	1.05	1.01	1.02	1.1	1.01	1.06
$(\frac{\text{AVR65}}{\text{AVR132}})$ nm	0.41	0.4	0.41	0.4	0.38	0.39

Table 4.16: Energy Comparisons 32-bit Math Test

For this case Figure 4.18b reveals that the implementations of the AVR on the 130nm library consume roughly the same power as the AVR32 65nm while the Figure 4.19b shows that the energy consumption of the AVR 65nm is roughly the same as the AVR32s based on the 130nm library. At the same time Figure 4.19a show that the AVR 65nm as a system consumes double the energy as the 130nm library based AVR32.

4.2.5.2 NTV and STV

(pJ)	65nm	130nm	130 ltd2	130 ltd
AVR				
Super TV	5070.56	12478.1	12778.2	13217.8
NTV	—	—	1201.15	1242.47
STV	—	—	—	951.679
AVR32				
Super TV	864.2	2228.36	2417.44	2489.36
NTV	—	—	227.239	234.
STV	—	—	—	179.234

Table 4.17: 32-bit Math Energy Estimation for NTV and STV

4.2.6 RAM Write Test

4.2.6.1 Super Threshold Voltage

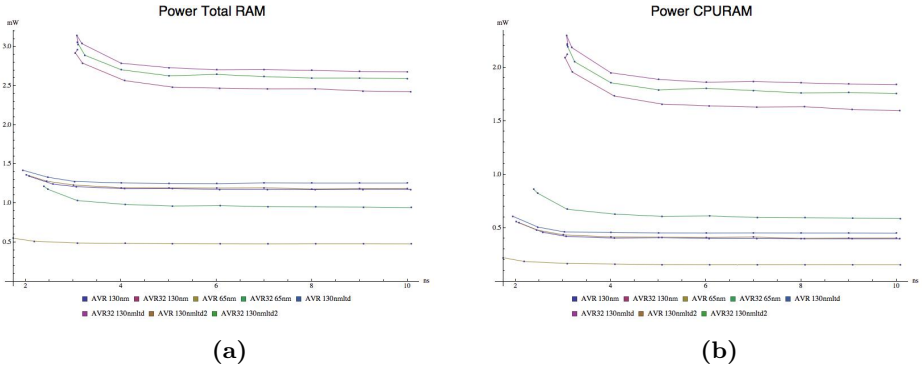


Figure 4.22: Power Graphs for the RAM Test

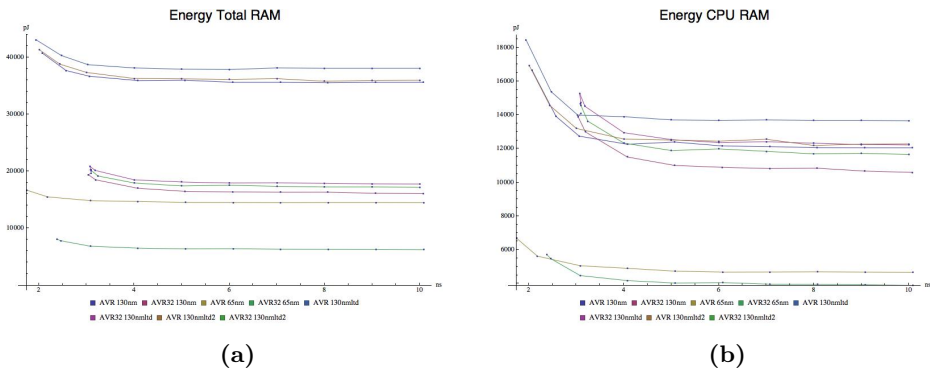


Figure 4.23: Energy Graphs for the RAM Test

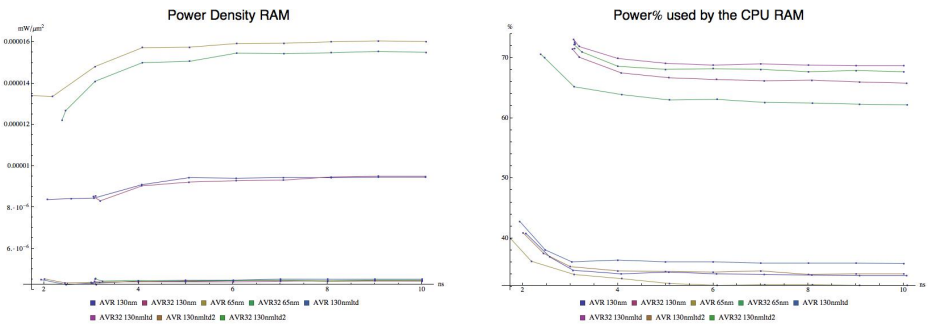


Figure 4.24: Power Density Graphs for the RAM Test

Figure 4.25: CPU % Power Graphs for the RAM Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$(\frac{AVR32}{AVR})130nm$	2.35	2.06	2.16	4.66	3.87	4.18
$(\frac{AVR32}{AVR})130nm1td$	2.38	2.13	2.2	4.74	3.6	4.19
$(\frac{AVR32}{AVR})130nm1td2$	2.39	2.18	2.24	4.72	3.98	4.39
$(\frac{AVR32}{AVR})65nm$	2.3	1.97	2.06	4.45	3.81	3.95
$(\frac{AVR321td}{AVR32})130nm$	1.1	1.02	1.09	1.15	1.03	1.12
$(\frac{AVR321td2}{AVR32})130nm$	1.07	1.03	1.06	1.1	1.04	1.08
$(\frac{AVR3265}{AVR32130})nm$	0.41	0.37	0.39	0.4	0.34	0.37
$(\frac{AVR1td}{AVR})130nm$	1.07	1.05	1.06	1.14	1.1	1.12
$(\frac{AVR1td2}{AVR})130nm$	1.03	1.01	1.01	1.05	1.01	1.02
$(\frac{AVR65}{AVR130})nm$	0.41	0.4	0.41	0.4	0.38	0.39

Table 4.18: Power Comparisons RAM Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$(\frac{AVR32}{AVR})130nm$	0.51	0.45	0.47	1.02	0.85	0.91
$(\frac{AVR32}{AVR})130nm1td$	0.52	0.47	0.48	1.04	0.79	0.92
$(\frac{AVR32}{AVR})130nm1td2$	0.52	0.48	0.49	1.03	0.87	0.96
$(\frac{AVR32}{AVR})65nm$	0.5	0.43	0.45	0.97	0.83	0.86
$(\frac{AVR321td}{AVR32})130nm$	1.1	1.02	1.09	1.15	1.03	1.12
$(\frac{AVR321td2}{AVR32})130nm$	1.07	1.03	1.06	1.1	1.04	1.08
$(\frac{AVR3265}{AVR32130})nm$	0.41	0.37	0.39	0.4	0.34	0.37
$(\frac{AVR1td}{AVR})130nm$	1.07	1.05	1.06	1.14	1.1	1.12
$(\frac{AVR1td2}{AVR})130nm$	1.03	1.01	1.01	1.05	1.01	1.02
$(\frac{AVR65}{AVR132})nm$	0.41	0.4	0.41	0.4	0.38	0.39

Table 4.19: Energy Comparisons RAM Test

In the case of RAM test Figure 4.22a shows that the AVR 130nmltd2 system, is very close to the AVR 130nm one. It stands out that the AVR32 65nm system is close to the AVR130nm based Figure 4.22b show us a larger consumption by the AVR32 65nm core than any of the AVRs. On the energy side the AVR 65nm system consume slightly less energy than any of the AVR32 130nm spawned systems as seen on the Figure 4.23a. Meanwhile Figure 4.23b show us a more complex picture where the AVR32 130nm based CPUs consume less energy than the AVR 130nm ones above the 5ns target. The Figure 4.24 shows three distinct on the top the 65nm based systems followed by the AVR and AVR32 130nm -the ones that us the full library- and the rest at the bottom. Figure 4.25 shows two groups the AVR32 on the top between 62% and 72% and the AVR between 38% and 41%

4.2.6.2 NTV and STV

(pJ)	65nm	130nm	130 ltd2	130 ltd
AVR				
Super TV	14502.5	35649.5	36013.6	38107.
NTV	—	—	3385.28	3582.06
STV	—	—	—	2743.71
AVR32				
Super TV	6261.52	16095.4	17210.9	17781.9
NTV	—	—	1617.82	1671.5
STV	—	—	—	1280.3

Table 4.20: RAM Energy Estimation for NTV and STV

4.2.7 SPI Read and Write Test

4.2.7.1 Super Threshold Voltage

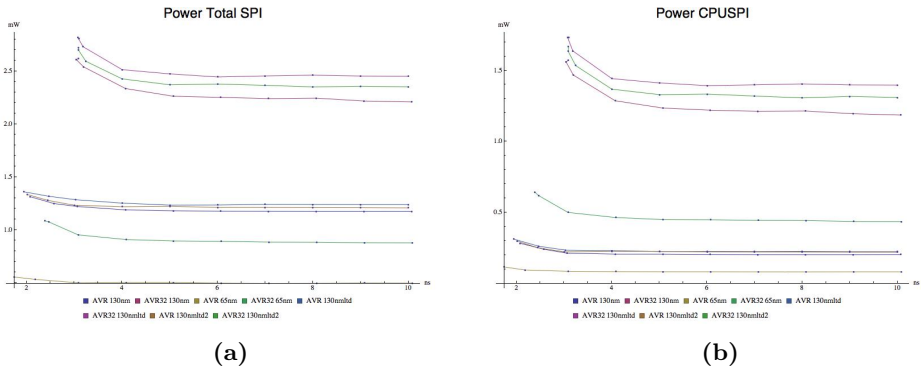


Figure 4.26: Power Graphs for the SPI Test

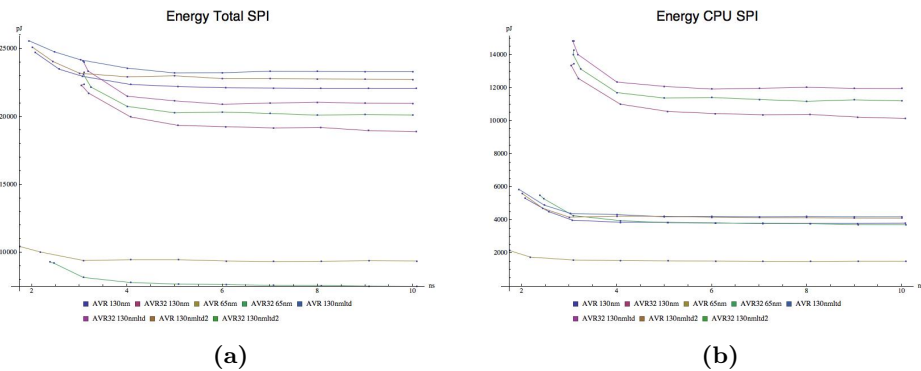


Figure 4.27: Energy Graphs for the SPI Test

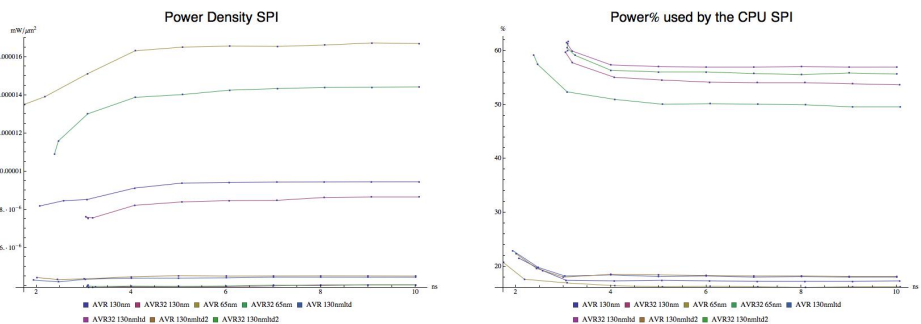


Figure 4.28: Power Density Graphs for the SPI Test

Figure 4.29: CPU % Power Graphs for the SPI Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nm	2.09	1.88	1.95	6.91	5.57	6.1
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd	2.14	1.98	2.02	7.	5.57	6.31
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd2	2.11	1.94	1.99	6.91	5.6	6.09
$(\frac{\text{AVR32}}{\text{AVR}})$ 65nm	2.02	1.76	1.83	6.6	5.39	5.66
$(\frac{\text{AVR32ltd}}{\text{AVR32}})$ 130nm	1.11	1.07	1.09	1.18	1.1	1.14
$(\frac{\text{AVR32ltd2}}{\text{AVR32}})$ 130nm	1.06	1.02	1.05	1.1	1.05	1.08
$(\frac{\text{AVR3265}}{\text{AVR32130}})$ nm	0.42	0.38	0.4	0.41	0.34	0.37
$(\frac{\text{AVRltd}}{\text{AVR}})$ 130nm	1.06	1.04	1.05	1.12	1.09	1.1
$(\frac{\text{AVRltd2}}{\text{AVR}})$ 130nm	1.04	1.01	1.03	1.1	1.04	1.08
$(\frac{\text{AVR65}}{\text{AVR130}})$ nm	0.43	0.41	0.42	0.41	0.39	0.4

Table 4.21: Power Comparisons SPI Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nm	0.95	0.86	0.89	3.14	2.53	2.77
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd	0.97	0.9	0.92	3.19	2.53	2.87
$(\frac{\text{AVR32}}{\text{AVR}})$ 130nmltd2	0.96	0.88	0.91	3.14	2.55	2.77
$(\frac{\text{AVR32}}{\text{AVR}})$ 65nm	0.92	0.8	0.83	3.	2.45	2.57
$(\frac{\text{AVR32ltd}}{\text{AVR32}})$ 130nm	1.11	1.07	1.09	1.18	1.1	1.14
$(\frac{\text{AVR32ltd2}}{\text{AVR32}})$ 130nm	1.06	1.02	1.05	1.1	1.05	1.08
$(\frac{\text{AVR3265}}{\text{AVR32130}})$ nm	0.42	0.38	0.4	0.41	0.34	0.37
$(\frac{\text{AVRltd}}{\text{AVR}})$ 130nm	1.06	1.04	1.05	1.12	1.09	1.1
$(\frac{\text{AVRltd2}}{\text{AVR}})$ 130nm	1.04	1.01	1.03	1.1	1.04	1.08
$(\frac{\text{AVR65}}{\text{AVR132}})$ nm	0.43	0.41	0.42	0.41	0.39	0.4

Table 4.22: Energy Comparisons SPI Test

The SPI power figures present the same case a similar behavior between the AVRs on the 130nm library and the AVR32 65nm. For the total system power expenditure shows that AVR32 above the 3ns target synthesis periods it consumes energy as shown by Figure 4.27a. Figure 4.27b Shows two groups the AVR 130nm based and AVR32 65nm on the bottom and the AVR32 130nm cores no the top.

4.2.7.2 NTV and STV

(pJ)	65nm	130nm	130 ltd2	130 ltd
AVR				
Super TV	9372.36	22094.7	22734.6	23318.
NTV	—	—	2137.05	2191.89
STV	—	—	—	1678.89
AVR32				
Super TV	7507.12	18900.5	20124.6	20980.6
NTV	—	—	1891.71	1972.17
STV	—	—	—	1510.6

Table 4.23: SPI Energy Estimation for NTV and STV

4.2.8 TCP/IP Checksum Computation Test

4.2.8.1 Super Threshold Voltage

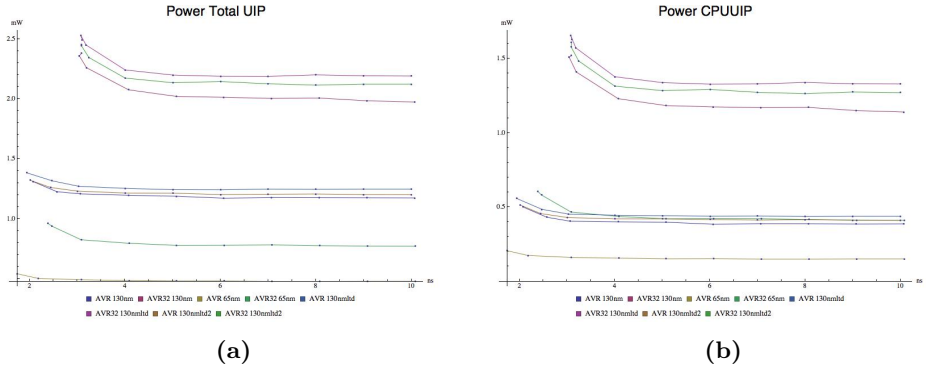


Figure 4.30: Power Graphs for the TCP/IP Checksum Test

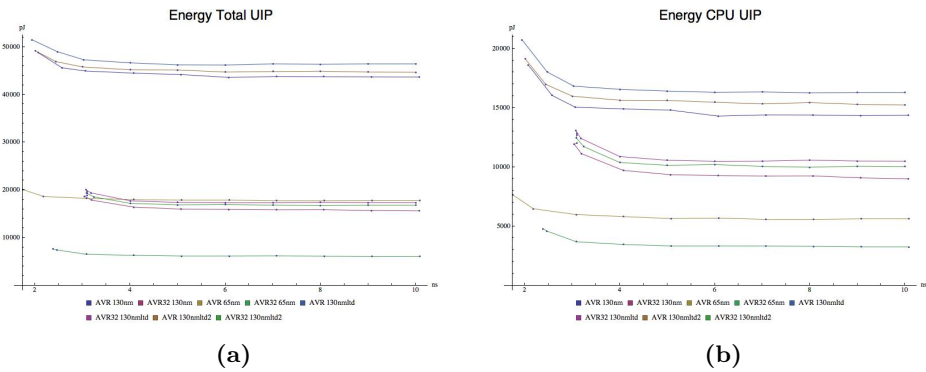


Figure 4.31: Energy Graphs for the TCP/IP Checksum Test

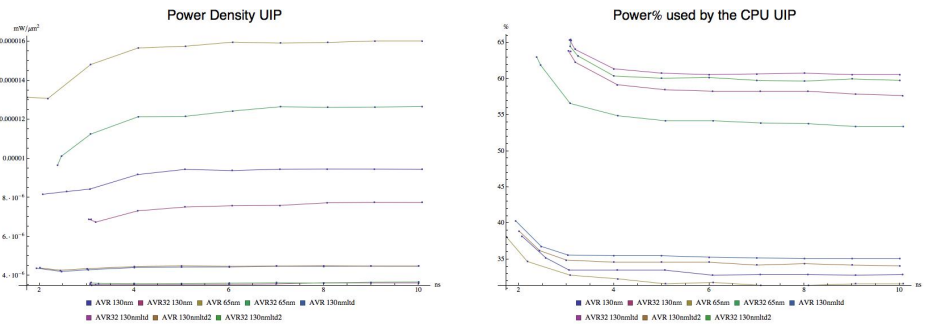


Figure 4.32: Power Density Graphs for the TCP/IP Checksum Test

Figure 4.33: CPU % Power Graphs for the TCP/IP Checksum Test

	Total Power			CPU Power		
	Max	Min	Mean	Max	Min	Mean
$(\frac{AVR32}{AVR})130nm$	1.93	1.68	1.76	3.5	2.95	3.11
$(\frac{AVR32}{AVR})130nm1td$	1.93	1.75	1.8	3.48	2.92	3.11
$(\frac{AVR32}{AVR})130nm1td2$	1.94	1.75	1.81	3.46	3.04	3.17
$(\frac{AVR32}{AVR})65nm$	1.87	1.61	1.67	3.34	2.72	2.86
$(\frac{AVR321td}{AVR32})130nm$	1.11	1.05	1.09	1.17	1.07	1.13
$(\frac{AVR321td2}{AVR32})130nm$	1.08	1.03	1.05	1.11	1.05	1.08
$(\frac{AVR3265}{AVR32130})nm$	0.4	0.36	0.39	0.4	0.33	0.36
$(\frac{AVR1td}{AVR})130nm$	1.07	1.05	1.06	1.14	1.11	1.13
$(\frac{AVR1td2}{AVR})130nm$	1.03	1.01	1.02	1.08	1.03	1.06
$(\frac{AVR65}{AVR130})nm$	0.41	0.4	0.41	0.41	0.38	0.39

Table 4.24: Power Comparisons TCP/IP Checksum Test

	Total Energy			CPU Energy		
	Max	Min	Mean	Max	Min	Mean
$(\frac{AVR32}{AVR})130nm$	0.41	0.36	0.37	0.74	0.63	0.66
$(\frac{AVR32}{AVR})130nm1td$	0.41	0.37	0.38	0.74	0.62	0.66
$(\frac{AVR32}{AVR})130nm1td2$	0.41	0.37	0.38	0.73	0.65	0.67
$(\frac{AVR32}{AVR})65nm$	0.4	0.34	0.35	0.71	0.58	0.61
$(\frac{AVR321td}{AVR32})130nm$	1.11	1.05	1.09	1.17	1.07	1.13
$(\frac{AVR321td2}{AVR32})130nm$	1.08	1.03	1.05	1.11	1.05	1.08
$(\frac{AVR3265}{AVR32130})nm$	0.4	0.36	0.39	0.4	0.33	0.36
$(\frac{AVR1td}{AVR})130nm$	1.07	1.05	1.06	1.14	1.11	1.13
$(\frac{AVR1td2}{AVR})130nm$	1.03	1.01	1.02	1.08	1.03	1.06
$(\frac{AVR65}{AVR132})nm$	0.41	0.4	0.41	0.41	0.38	0.39

Table 4.25: Energy Comparisons TCP/IP Checksum Test

Figure 4.30a and Figure 4.30b exhibits the same behavior Figure 4.18a and Figure 4.18b. Figure 4.31a shows that the energy consumed by the AVR 65nm system consumes more or less the same oiler as the AVR32 130nm library based systems. Figure 4.31b exposes that the AVR32 cores consume less power than the AVR ones -all form the 130nm library-

4.2.8.2 NTV and STV

(pJ)	65nm	130nm	130 ltd2	130 ltd
AVR				
Super TV	17791.2	43696.3	44701.2	46450.6
NTV	—	—	4201.91	4366.35
STV	—	—	—	3344.44
AVR32				
Super TV	6083.	15610.4	16787.5	17324.7
NTV	—	—	1578.03	1628.52
STV	—	—	—	1247.38

Table 4.26: TCP/IP Checksum Energy Estimation for NTV and STV

4.2.9 Summary

For the super- threshold voltage operation it has been shown the power consumption of the *AVR32* core is from 2.4 to 7 times (been 3.7 the mean) than the *AVR* core but the energy spent by the *AVR32* core is from 0.3 to 3.2 times (been 1.2 the mean) the *AVR*. At the same time the total power consumed by the system -core, bus and peripherals- when using the *AVR32* form 1.5 to 2.4 times larger (been 1.8 the mean) while in terms of energy expenditure when using the *AVR32* core is from 0.2 to 1 times (been 0.6 the mean) times the *AVR*.

For the *STV* and *NTV* estimations it is shown that is more effective to reduce de voltage than scaling to the 65nm library. For the *NTV* case using the 130ltd2 library is more effective than using the 130ltd.

Chapter 5

Discussion

This chapter is divided into four sections to point out the most interesting parts in a comprehensible way. First the synthesis process is discussed, then the results for the power and energy experiments, after that there are some suggestions along with some things I wanted to try and at the end the final conclusions are presented.

5.1 Synthesis

The synthesis was a very important part of this project. Overall the work on this area was sufficient for running the power and energy experiments. The reports generated provided useful insight into the net lists delivered by the synthesis tool. The libraries provided were good for the initial approach to get insight on how the different parameters affect the energy and power. It is worth remembering that most of the algorithms used for the synthesis are non-exact and heuristics since the problems solved by the tool are NP problems. It is very unlikely that the synthesis finds an optimal solution. Particularly interesting is the case of the net list for the AVR 130nm1td2 targeting 3ns that proves to be more efficient than other more relaxed net-lists.

5.1.1 Area

The results for the area were as expected, systems based on larger cores took a larger area, smaller feature size libraries led to smaller footprints. Restricting the library forced the tool to find a larger solution and targeting a smaller clock period ended in a larger net list as less logic depth is allowed until some point is reached where the area increases a lot but the timing is not met.

5.1.2 Timing

The synthesis tool was able to hit the targeted clock period with some error until it was so constrained that no solution was found and for some synthesis the achieved

time is larger than a previous solution and takes a larger area.

5.2 Power and Energy

Several experiments have been done on this work to watch the influence on power and energy. Two cores were tested, different libraries were used and different conditions for a library were imposed to make it more suitable for a *STV* and *NTV*. The system is very limited in terms of number of peripherals and small memory. This emphasizes the roll that the *CPU* has on the overall amount of power and energy used.

5.2.1 AVR vs AVR32

The heterogeneous architectures seen in Section 2.2 the cores are similar. For the *Kal-El* they have different implementation of the same core and for the *big.LITTLE* the same piece of code can be executed on both cores. While on this thesis the same C code had to be compiled, assembled and linked by a set of tools of the *AVR* and *AVR32*, producing executable code that can not be executed on the that was not intended to. On top of that the *AVR* is an 8-bit *CPU* and *AVR32* is a 32-bit *CPU*. If this is not different enough on top of that they interface with the system on different busses adding complexity to the system and motivates to find out which tasks are more energy efficient to be done on one core or another. All this differences en up boiling in to three main contributing factors. Data width, execution time a task takes and power consumed by the computation.

The *AVR* can only perform 8-bit operations while the *AVR32* can perform 32-bit operations. This mean that the *AVR* will require several operations to do a 32-bit math operation which is a clear disadvantage if there are a lot of 32-bit operations. But not the other if the operations are 8 bit the hardware of the *AVR32* is too large and still consumes power and energy even if no useful work is done.

The *AVR32* consumes more power than the *AVR* which might give us the idea that on the long run the *AVR32* will be more expensive to operate. That is particularly good for the system is limited in power. Power can be limited because the power source is limited or there is a constraint on the amount of heat that can be removed.

Execution time is very important for real time applications where knowing how much time a task will take is needed to guarantee the task will meet the deadline. But also is important because is needed to compute the total energy performing a task will take. It is possible that a *CPU* requiring higher power but requiring less time use less energy for solving the same task as a low power *CPU* that takes a longer time to finish the task. As a matter of fact this is the main reason why the systems based on the on the *AVR32* use less energy for competing the tests than

the AVR except for the cases where the difference of the execution time is not large enough to counter the extra expenditure on power like 8-bit switch test. In which the AVR just takes 1.73 times the time than for the AVR32.

5.2.2 Core vs System

As seen with the test cases for SPI, 16-bit switch and RAM the CPU energy expenditure does not explain why the AVR32 based systems use less energy than the AVR based systems use less energy on the task overall. That is the rest of the peripherals contribution. Even on the RAM test case -the one where the CPUs use the maximum energy share up to 70%- the system contribution is enough to make the AVR32 systems use less energy. It is theoretically possible to have a large enough system where the CPU choice does not make a difference on the power, and energy profile. As a matter of fact if the peripherals were turned off during the RAM test the systems based on the AVR would have been the more energy efficient.

5.2.3 NTV and STV

If the assumptions stated on Section 3.3.2 apply choosing least energy expenditure implementation of the core then depends on the voltage management philosophy. If it is STV and it is fixed then the 130nm1td is the best alternative. If for some reason dynamic voltage is needed (to adjust performance to work load) and the STV is not needed then the best way to go is with the 130nm1td2 approach. If the system is limited to super-threshold voltage then 130nm (without restrictions) will provide the lowest energy/power footprint.

5.3 Future Work

There are a lot of interesting ways to extend the range of this project. To have a better picture on how better to adapt to different conditions that might present in different applications.

5.3.1 Test Cases and Peripherals

More cases must be added and profiled. some of them might be memories with wait states, burst transactions shared caches, multiple masters trying to access a slave simultaneously, interrupts, DMAs, going to/ waking from sleep states, sleep states, watchdog routines, encryption etc. On the peripherals side USART, bluetooth, ethernet, USB and ADCs, RFID readers are a good place to start to get a broader picture on the huge set of applications useful under the IoT scope.

Other interesting thing will be to include the ability to turn on or off different peripherals to quantify the contributions of them on the system and ultimately will end giving the final application better control on the energy and power expenditure.

5.3.2 Real STV, NTV and More Libraries

As stated earlier there was no STV nor NTV library available for this project. Performing the synthesis on such libraries will yield to more accurate results and provide a more detail picture on the effects on power, leakage and timing. The use of other libraries featuring different sizes will provide a better understanding on the effects of seizing.

5.3.3 Tools and Testing Cores at the Same Time

The development of tools that address both cores at the same time will speed up the generation and testing of cases. An interesting idea is to be able to target an optimization target like performance, energy, power and permit the cooperation between cores.

Also it is important to understand how the handover of tasks and the address of shared resources affect the time a task takes, the power it draws, etc.

5.3.4 Cores

To test other cores (AVR AP7, megaAVR, tinyAVR and /or ARM Cortex M0+) and different set-ups will help to encounter more suitable solutions to other environments and applications.

5.4 Conclusions

This project has shown the great diversity provided by testing two different cores, in one intense we have that the AVR32 is in general terms more energy efficient than the AVR because it takes less time to do things. On the other hand if the main source of power is a harvesting system that can not provide peaks of power but a moderate supply then the AVR would be better since is easier to make it comply to the power constrain.

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